

MILITARY SPECIFICATION

MICROCIRCUITS, LINEAR, 8 BIT,
DIGITAL-TO-ANALOG CONVERTERS,
MONOLITHIC SILICON

This specification is approved for use by all Departments and Agencies of the Department of Defense.

1. SCOPE

1.1 Scope. This specification covers the detail requirements for monolithic silicon, 8 bit, digital-to-analog converters. Three product assurance classes are provided for each type and are reflected in the complete part number.

1.2 Part number. The complete part number shall be in accordance with MIL-M-38510.

1.2.1 Device type. The device types shall be as follows:

<u>Device type</u>	<u>Circuit</u>
01	D/A Converter, 8 bit, 0.19% linearity
02	D/A Converter, 8 bit, 0.10% linearity

1.2.2 Device class. The device class shall be the product assurance level as defined in MIL-M-38510.

1.2.3 Case outline. The case outline shall be designated as follows:

<u>Outline letter</u>	<u>MIL-M-38510, appendix C, case outline</u>
E	D-2 (16 lead, 1/4" x 7/8", dual-in-line)

1.3 Absolute maximum ratings.

Supply voltage $[+V_{CC} - (-V_{CC})]$	- - - - - 36 Vdc
Voltage, digital input to negative supply $[V_{logic} - (-V_{CC})]$	- - - - - 0 to 36 Vdc
Voltage, logic control (V_{LC})	- - - - - $-V_{CC}$ to $+V_{CC}$
Reference voltage input (V_{14}, V_{15})	- - - - - $-V_{CC}$ to $+V_{CC}$
Reference input current (I_{14})	- - - - - 5.0 mA
Reference input differential voltage $[(V_{14} - V_{15})]$	- - - - - ± 18 Vdc
Lead temperature (soldering, 60 sec.)	- - - - - 300°C
Junction temperature	- - - - - 175°C
Storage temperature	- - - - - -65°C to +150°C

1.4 Recommended operating conditions.

Supply voltage range	- - - - - ± 5 Vdc to ± 15 Vdc
Ambient temperature range	- - - - - -55°C to +125°C

1/ A slight degradation in linearity can occur when the supply voltage is near the ± 5 V end of the recommended operating range.

Beneficial comments (recommendations, additions, deletions) and any pertinent data which may be of use in improving this document should be addressed to: Rome Air Development Center, (RBRD), Griffis AFB, NY 13441, by using the self-addressed Standardization Document Improvement Proposal (DD Form 1426) appearing at the end of this document or by letter.

1.5 Power and thermal characteristics.

<u>Package</u>	<u>Case outline</u>	<u>Maximum allowable power dissipation</u>	<u>Maximum ΘJ - C</u>	<u>Maximum ΘJ - A</u>
Dual-in-line	E	400 mW @ $T_A = 125^\circ\text{C}$	35°C/W	120°C/W

2. APPLICABLE DOCUMENTS

2.1 Issues of documents. The following documents of the issue in effect on date of invitation for bids or request for proposal, form a part of this specification to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics

(Copies of specifications, standards, drawings, and publications required by contractors in connection with specific procurement functions should be obtained from the procuring activity or as directed by the contracting officer.)

3. REQUIREMENTS

3.1 Detail specifications. The individual item requirements shall be in accordance with MIL-M-38510, and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections and block diagram shall be as specified on figure 1.

3.2.2 Schematic circuit. The schematic circuit shall be as specified on figure 2.

3.2.3 Case outline. Case outline shall be as specified in 1.2.3.

3.3 Lead material and finish. Lead material and finish shall be in accordance with MIL-M-38510.

3.4 Electrical performance characteristics. The following electrical performance characteristics apply unless otherwise stated in table I:

$\pm V_{CC} = \pm 15 \text{ Vdc}$ Source resistance = 50 ohms $I_{REF} = 2.0 \text{ mA}$
 Ambient temperature range = -55°C to $+125^\circ\text{C}$

3.5 Rebonding. Rebonding shall be in accordance with MIL-M-38510.

TABLE I. Electrical performance characteristics.

Characteristics	Symbol	Conditions: 3.4, table III and figures 6, 7, and 8	Device				Units
			O1 limits	O2 limits	Min	Max	
Supply current from +V _{CC}	I _{CC} ⁺	All input bits high	0.4	3.8	0.4	3.8	mA
Supply current from -V _{CC}	I _{CC} ⁻	All input bits high	-7.8	-0.8	-7.8	-0.8	mA
Full scale current	I _{FS}	All input bits high, T _A = 25°C Measure I ₀	1.94	2.04	1.984	2.000	mA
	I _{FS}	All input bits low, T _A = 25°C Measure I ₀	1.94	2.04	1.984	2.000	mA
Zero scale current	I _{ZS}	All input bits low, Measure I ₀	-2.0	2.0	-1.0	1.0	μA
	I _{ZS}	All input bits high, Measure I ₀	-2.0	2.0	-1.0	1.0	μA
Power supply sensitivity from +V _{CC}	P _{SS} I _{FS+1}	All input bits high, Measure I ₀ , +V _{CC} = 4.5 V to +5.5 V, -V _{CC} = -18 V	-4.0	4.0	-4.0	4.0	μA
	P _{SS} I _{FS+1}	All input bits low, Measure I ₀ , +V _{CC} = 4.5 V to +5.5 V, -V _{CC} = -18 V	-4.0	4.0	-4.0	4.0	μA
Power supply sensitivity from +V _{CC}	P _{SS} I _{FS+2}	All input bits high, Measure I ₀ , +V _{CC} = 12 V to 18 V, -V _{CC} = -18 V	-8.0	8.0	-8.0	8.0	μA
	P _{SS} I _{FS+2}	All input bits low, Measure I ₀ , +V _{CC} = 12 V to 18 V, -V _{CC} = -18 V	-8.0	8.0	-8.0	8.0	μA
Power supply sensitivity from -V _{CC}	P _{SS} I _{FS-1}	All input bits high, Measure I ₀ , +V _{CC} = 18 V, -V _{CC} = -12 V to -18 V	-8.0	8.0	-8.0	8.0	μA
	P _{SS} I _{FS-1}	All input bits low, Measure I ₀ , +V _{CC} = 18 V, -V _{CC} = -12 V to -18 V	-8.0	8.0	-8.0	8.0	μA
Power supply sensitivity from -V _{CC}	P _{SS} I _{FS-2}	All input bits high, Measure I ₀ , +V _{CC} = 18 V, -V _{CC} = -4.5 V to -5.5 V	-2.0	2.0	-2.0	2.0	μA
	P _{SS} I _{FS-2}	All input bits low, Measure I ₀ , +V _{CC} = 18 V, -V _{CC} = -4.5 V to -5.5 V	-2.0	2.0	-2.0	2.0	μA
Output current range	I _{FSR1}	All input bits high, Measure I ₀ , -V _{CC} = -10 V, V _{REF} = 15 V	2.1	---	2.1	---	mA
	I _{FSR1}	All input bits low, Measure I ₀ , -V _{CC} = -10 V, V _{REF} = 15 V	2.1	---	2.1	---	mA
Output current range	I _{FSR2}	All input bits high, Measure I ₀ , -V _{CC} = -12 V, V _{REF} = 25 V	4.2	---	4.2	---	mA
	I _{FSR2}	All input bits low, Measure I ₀ , -V _{CC} = -12 V, V _{REF} = 25 V	4.2	---	4.2	---	mA

TABLE I. Electrical performance characteristics - Continued.

Characteristics	Symbol	Conditions: 3.4, table III and figures 6, 7, and 8	Device				Units	
			01 limits	02 limits	Min	Max		
Reference bias current	I_{REF}^-	All input bits low	-3.0	0	-3.0	0	μA	
High level input current	I_{IH}	All input bits $V_{IN} = 18 V$, each input measured separately	-0.01	10.0	-0.01	10.0	μA	
Low level input current	I_{IL}	All input bits $V_{IN} = -10 V$, each input measured separately	-10.0	---	-10.0	---	μA	
Full scale current at +18 V compliance	I_{FS}^+	All input bits high, Measure I_0 , $V_{IO} = 18 V$	1.90	2.08	1.90	2.08	mA	
	\bar{I}_{FS}^+	All input bits low, Measure \bar{I}_0 , $V_{\bar{IO}} = 18 V$	1.90	2.08	1.90	2.08	mA	
Full scale current at -10 V compliance	I_{FS}^-	All input bits high, Measure I_0 , $V_{IO} = -10 V$	1.90	2.08	1.90	2.08	mA	
	\bar{I}_{FS}^-	All input bits low, Measure \bar{I}_0 , $V_{\bar{IO}} = -10 V$	1.90	2.08	1.90	2.08	mA	
Change in full scale current due to voltage compliance	ΔI_{FSC}	All input bits high, Measure I_0 , $V_{IO} = 18 V$ to -10 V	$25^\circ C \leq T_A \leq 125^\circ C$	-4.0	4.0	-4.0	4.0	μA
			$T_A = -55^\circ C$	-8.0	8.0	-8.0	8.0	μA
	$\Delta \bar{I}_{FSC}$	All input bits low, Measure \bar{I}_0 , $V_{\bar{IO}} = 18 V$ to -10 V	$25^\circ C \leq T_A \leq 125^\circ C$	-4.0	4.0	-4.0	4.0	μA
			$T_A = -55^\circ C$	-8.0	8.0	-8.0	8.0	μA
Positive bit errors	ΣNL^+	Measure I_0 (Σ Positive bit errors)/IFS	0	0.19	0	0.10	%	
	$\Sigma \bar{NL}^+$	Measure \bar{I}_0 (Σ Positive bit errors)/ \bar{IFS}	0	0.19	0	0.10	%	
Negative bit errors	ΣNL^-	Measure I_0 (Σ Negative bit errors)/IFS	-0.19	0	-0.10	0	%	
	$\Sigma \bar{NL}^-$	Measure \bar{I}_0 (Σ Negative bit errors)/ \bar{IFS}	-0.19	0	-0.10	0	%	
Positive and negative bit error difference	ΔNL	Measure I_0 $ NL^+ - NL^- $	-0.05	0.05	-0.03	0.03	%	
	$\Delta \bar{NL}$	Measure \bar{I}_0 $ \bar{NL}^+ - \bar{NL}^- $	-0.05	0.05	-0.03	0.03	%	
Positive relative accuracy	NL^+	Measure I_0 $ NL^+ + \Delta NL $	0	0.19	0	0.10	%	
	\bar{NL}^+	Measure \bar{I}_0 $ \bar{NL}^+ + \Delta \bar{NL} $	0	0.19	0	0.10	%	
Negative relative accuracy	NL^-	Measure I_0 $ NL^- + \Delta NL $	0	0.19	0	0.10	%	
	\bar{NL}^-	Measure \bar{I}_0 $ \bar{NL}^- + \Delta \bar{NL} $	0	0.19	0	0.10	%	

TABLE I. Electrical performance characteristics - Continued.

Characteristics	Symbol	Conditions: 3.4, table III and figures 6, 7, and 8	Device				Units
			01 limits		02 limits		
			Min	Max	Min	Max	
Monotonicity	$\Delta(i)$	Measure I_0 , $(I_{ON} - I_{ON-1}) \geq 0$ at each major carry point	0	16.0	0	16.0	μA
	$\Delta(\bar{i})$	Measure \bar{I}_0 , $(\bar{I}_{ON} - \bar{I}_{ON-1}) \geq 0$ at each major carry point	0	16.0	0	16.0	μA
Output symmetry	ΔI_{FS}	$I_{FS} - \bar{I}_{FS}$	-8.0	8.0	-4.0	4.0	μA
Full scale current temperature coefficient	$T_C(I_{FS})$	All input bits high, Measure I_0	-50.0	50.0	-50.0	50.0	$ppm/^\circ C$
	$T_C(\bar{I}_{FS})$	All input bits low, Measure \bar{I}_0	-50.0	50.0	-50.0	50.0	$ppm/^\circ C$
Propagation delay time, high-to-low level	t_{PHL}	Figure 7, Measure V_0	6.0	60.0	6.0	60.0	ns
Propagation delay time, low-to-high level	t_{PLH}	Figure 7, Measure V_0	6.0	60.0	6.0	60.0	ns
Reference amplifier input slew rate	dI_0/dt	Figure 8, Measure V_0	1.5	---	1.5	---	$mA/\mu s$
Settling time high-to-low level	t_{SHL}	Figure 7, Output within 1/2 LSB of final value of I_0	10	135	10	135	ns
Settling time low-to-high level	t_{SLH}	Figure 7, Output within 1/2 LSB of final value of I_0	10	135	10	135	ns

3.6 Electrical test requirements. Electrical test requirements shall be as specified in table III for the applicable device type and device class. The subgroups of table III and limits of table IV which constitute the minimum electrical test requirements for screening, qualification and quality conformance, by device class are specified in table II.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirement	Subgroups (see table III)		
	Class S devices	Class B devices	Class C devices
Interim electrical parameters (Pre burn-in) (method 5004)	1	1	None
Final electrical test parameters (method 5004)	1*, 2, 3	1*, 2, 3	1
Group A test requirements (method 5005)	1, 2, 3, 9, 10, 11	1, 2, 3, 9, 10, 11	1, 2, 3, 9
Group C end point and group B, class S, electrical parameters (method 5005)	1, 2, 3, and table IV delta limits	1 and table IV delta limits	1 and table IV delta limits
Additional electrical subgroups for group C periodic inspections	Not applicable	12	10, 11, 12
Group D end point electrical parameters (method 5005)	1, 2, 3	1	1

* PDA applies to subgroup 1 (see 4.3d).

3.7 Marking. Marking shall be in accordance with MIL-M-38510 and 1.2. At the option of the manufacturer, the following marking may be omitted from the body of the microcircuit, but shall be retained on the initial container.

a. Country of origin.

3.8 Microcircuit group assignment. The devices covered by this specification shall be in microcircuit group number 56 (see MIL-M-38510, appendix E).

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883, except as modified herein.

4.2 Qualification inspection. Qualification inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified herein for groups A, B, C, and D inspections (see 4.4.1, 4.4.2, 4.4.3, and 4.4.4).

4.3 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to qualification and quality conformance inspection. The following additional criteria shall apply:

a. Burn-in (method 1015 of MIL-STD-883).

1. For class S devices: Test condition D using the circuit shown in figure 3.
2. For class B devices: Test condition D using the circuit shown in figure 3, test condition C using the circuit shown in figure 4, or test condition F using the circuit shown in figure 5.

NOTE: If accelerated high-temperature test conditions are used, the device manufacturer shall ensure that at least 85 percent of the applied voltage is dropped across the device at temperature. The device is not considered functional under accelerated test conditions.

- b. Reverse bias burn-in (method 1015 of MIL-STD-883). For class S devices only using the circuit shown on figure 4.
- c. Interim electrical parameters shall be performed for class S and B devices and shall be as specified in table II herein.
- d. Percent defective allowable (PDA) - The PDA for class S devices shall be as specified in MIL-M-38510. The PDA is specified as 10 percent for class B devices based on failures from group A, subgroup 1 test after cooldown as final electrical test in accordance with method 5004 of MIL-STD-883 and with no intervening electrical measurements. If interim electrical parameter tests are performed prior to burn-in, failures resulting from pre burn-in screening may be excluded from the PDA. If interim electrical parameter tests prior to burn-in are omitted, then all screening failures shall be included in the PDA. The verified failures of group A, subgroup 1 after burn-in in that lot shall be used to determine the percent defective for that lot, and the lot shall be accepted or rejected based on the PDA for the applicable device class.

4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, and D inspections (see 4.4.1, 4.4.2, 4.4.3, and 4.4.4).

4.4.1 Group A inspection. Group A inspection shall be in accordance with table I of method 5005 of MIL-STD-883 and as follows:

- a. Subgroups 4, 5, 6, 7, and 8 shall be omitted.
- b. Tests shall be as specified in table II herein.

4.4.2 Group B inspection. Group B inspection shall be in accordance with table II of method 5005 of MIL-STD-883 and as follows:

- a. End point electrical parameters shall be as specified in table II herein.
- b. Life test for class S devices shall be in accordance with table IIa (subgroup 5) of method 5005 of MIL-STD-883, using the circuit on figure 5. If the alternate burn-in conditions are used, the circuit on figure 3 shall be used.

4.4.3 Group C inspection. Group C inspection shall be in accordance with table III of method 5005 of MIL-STD-883 as follows:

- a. End point electrical parameters shall be as specified in table II herein.
- b. Life tests for class B and C (method 1005 of MIL-STD-883): Test condition D using the circuit shown on figure 3 or test condition F using the circuit shown on figure 5 (see 4.3a.2, note).

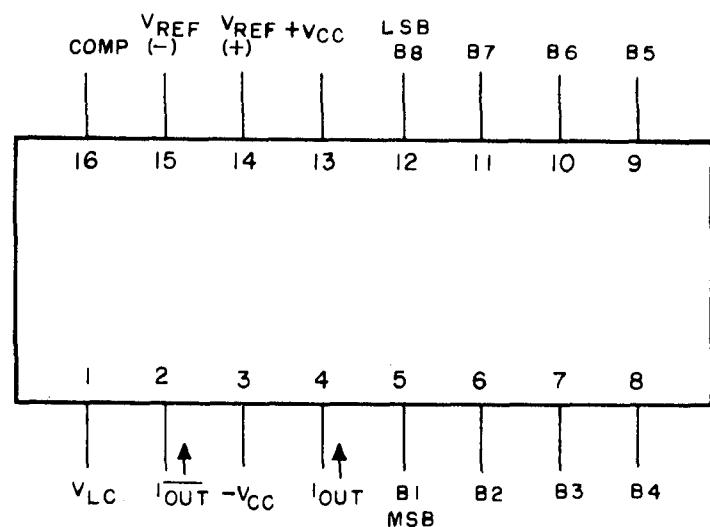
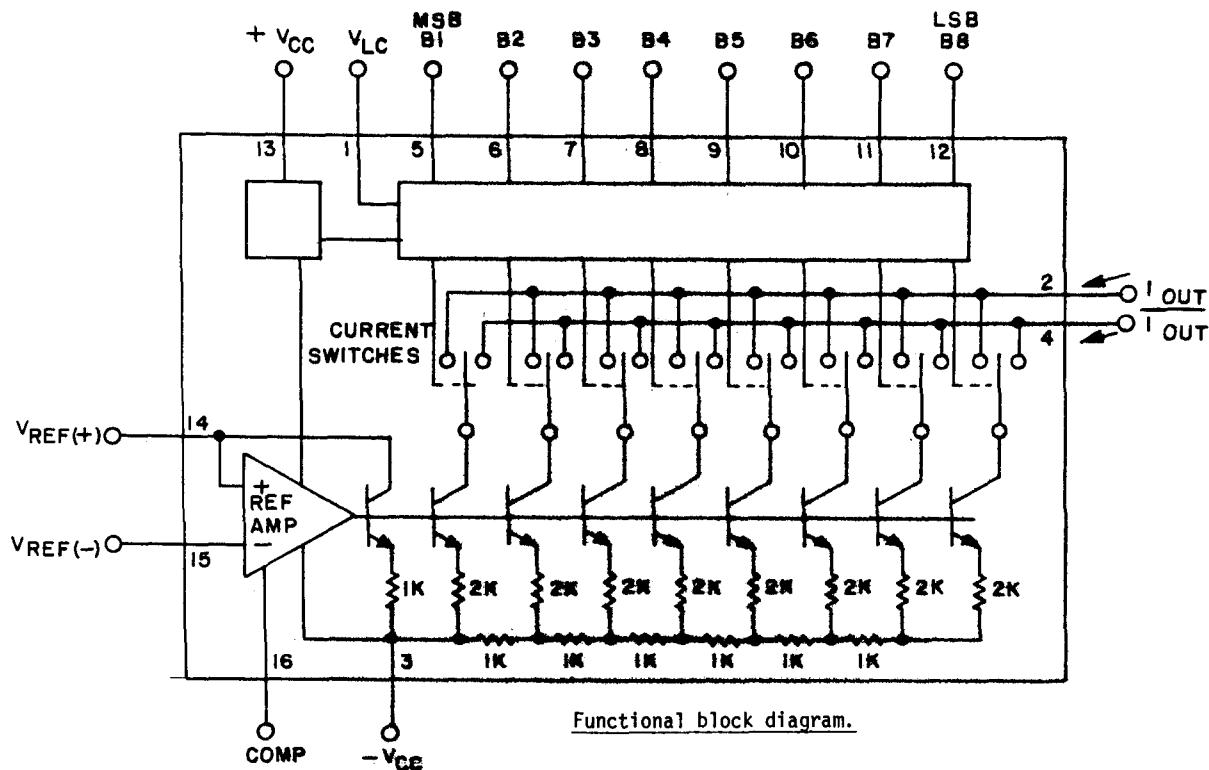
4.4.4 Group D inspection. Group D inspection shall be in accordance with table IV of method 5005 of MIL-STD-883 and end point electrical parameters shall be as specified in table II herein.

4.5 Methods of examination and test. Methods of examination and test shall be as specified in the appropriate tables. Electrical test circuits as prescribed herein or in the referenced test methods of MIL-STD-883 shall be acceptable. Other test circuits shall require the approval of the qualifying activity.

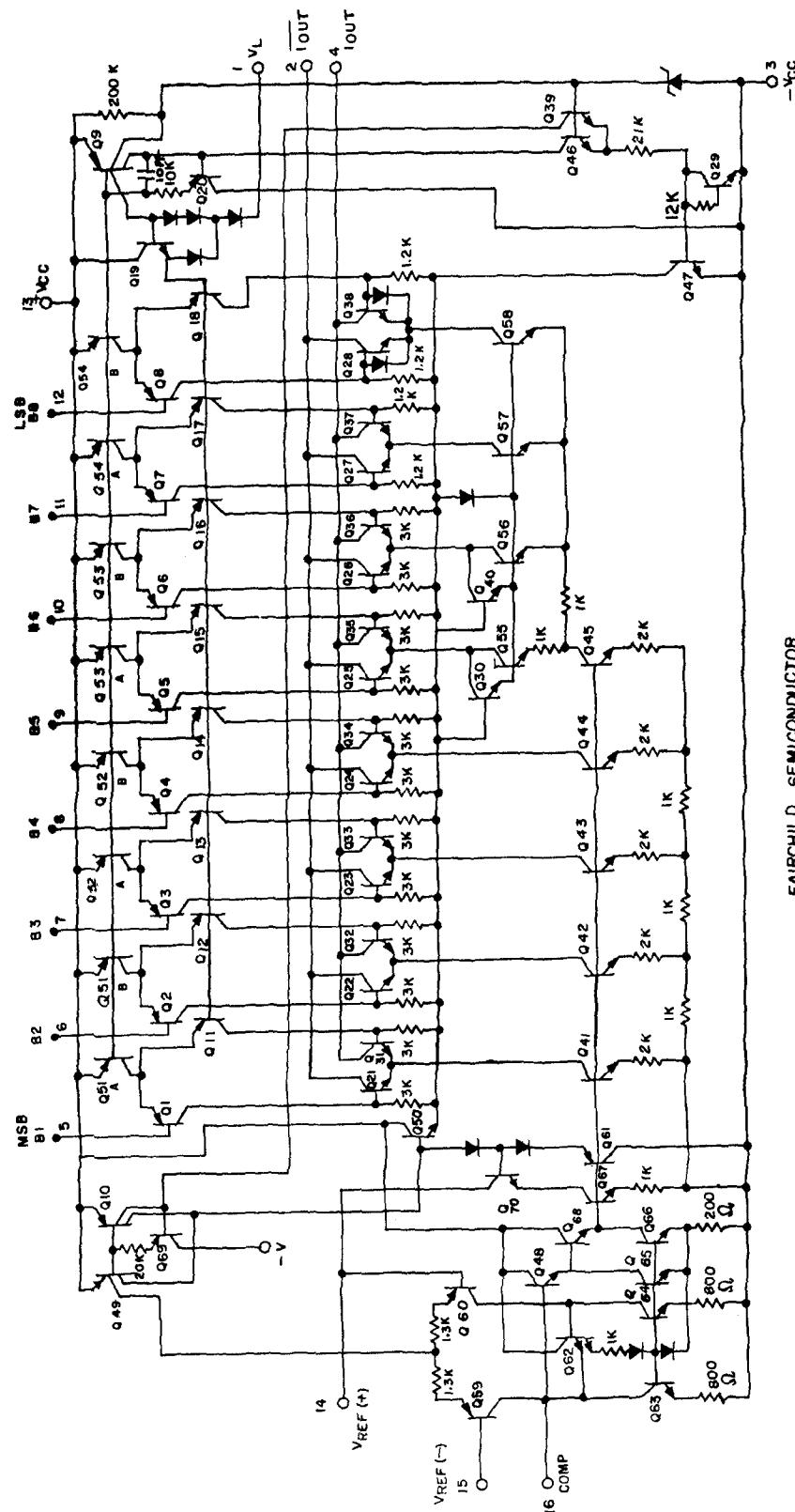
4.5.1 Voltage and current. All voltage values given, except the input offset voltage (or differential voltage) are referenced to the external zero reference level of the supply voltage. Currents given are conventional current and positive when flowing into the referenced terminal.

4.5.2 Life test cooldown procedure. When devices are measured at 25°C following application of the operating life or burn-in test condition, they shall be cooled to room temperature prior to removal of the bias.

4.6 Inspection of preparation for delivery. Inspection of preparation for delivery shall be in accordance with MIL-M-38510, except that the rough handling test shall not apply.

Terminal connections.Figure 1. Terminal connections and functional block diagram.

Device types 01 and 02



FAIRCHILD SEMICONDUCTOR

FIGURE 2. Schematic circuits.

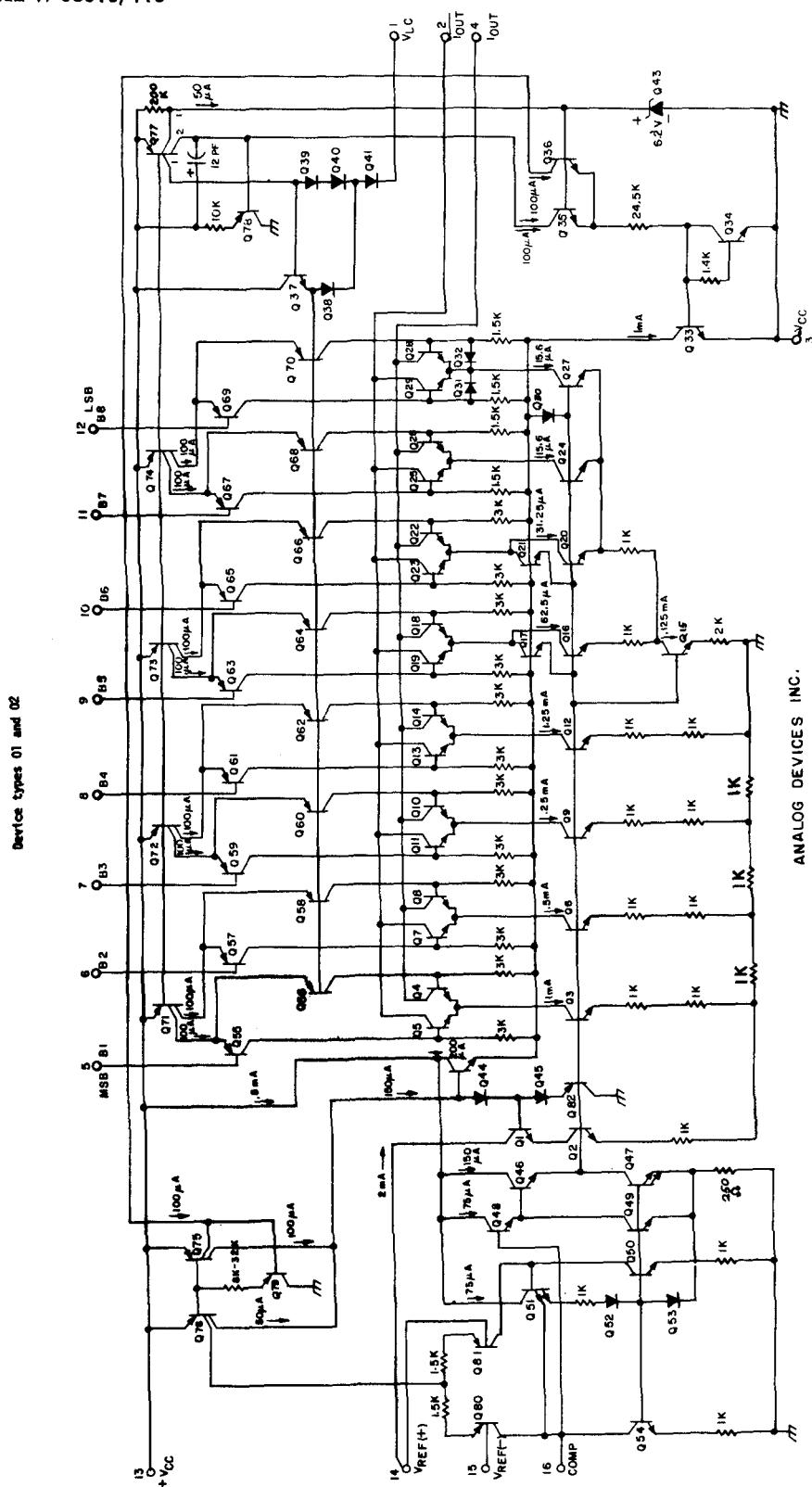
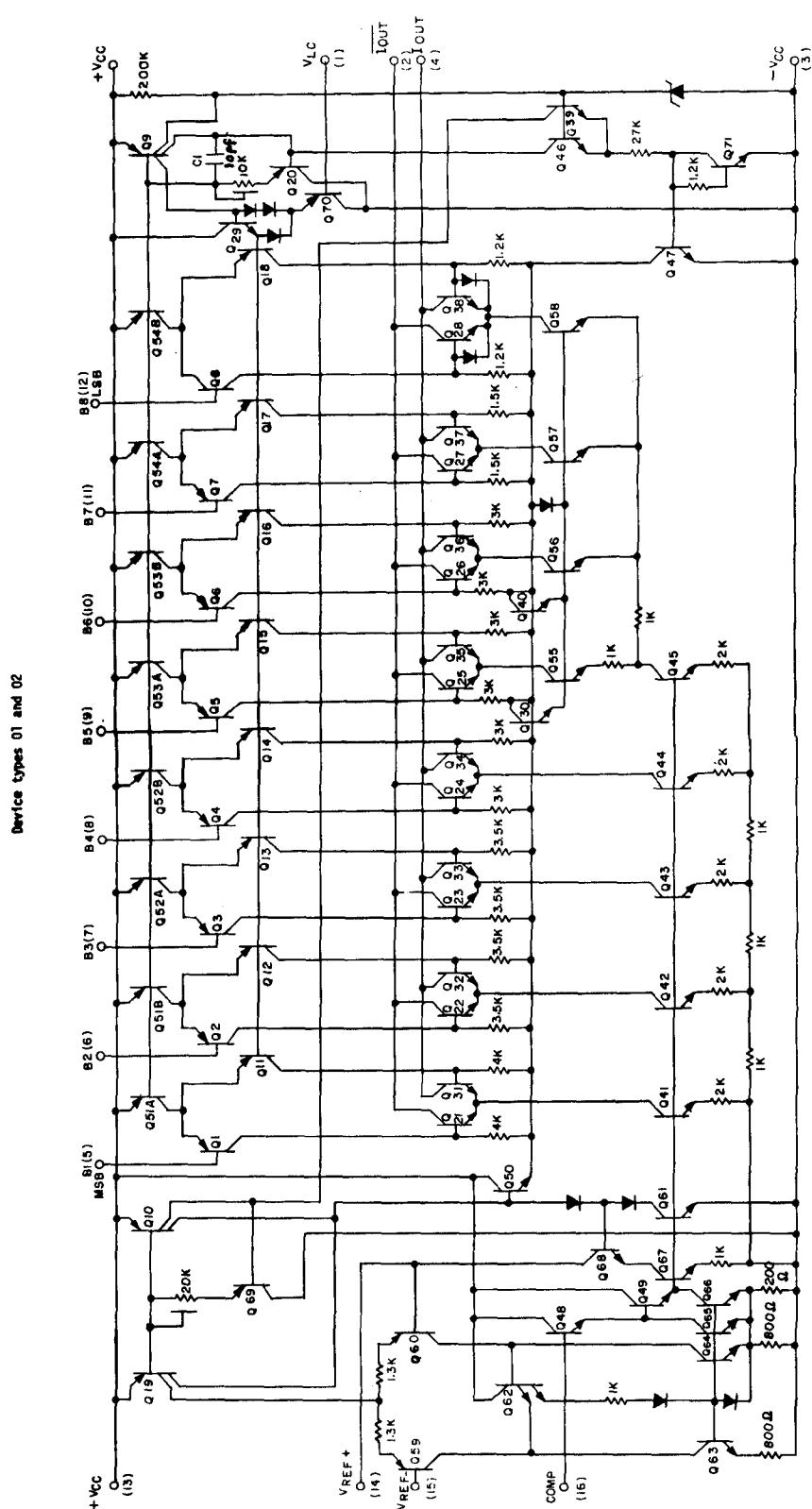


FIGURE 2. Schematic circuits - Continued.



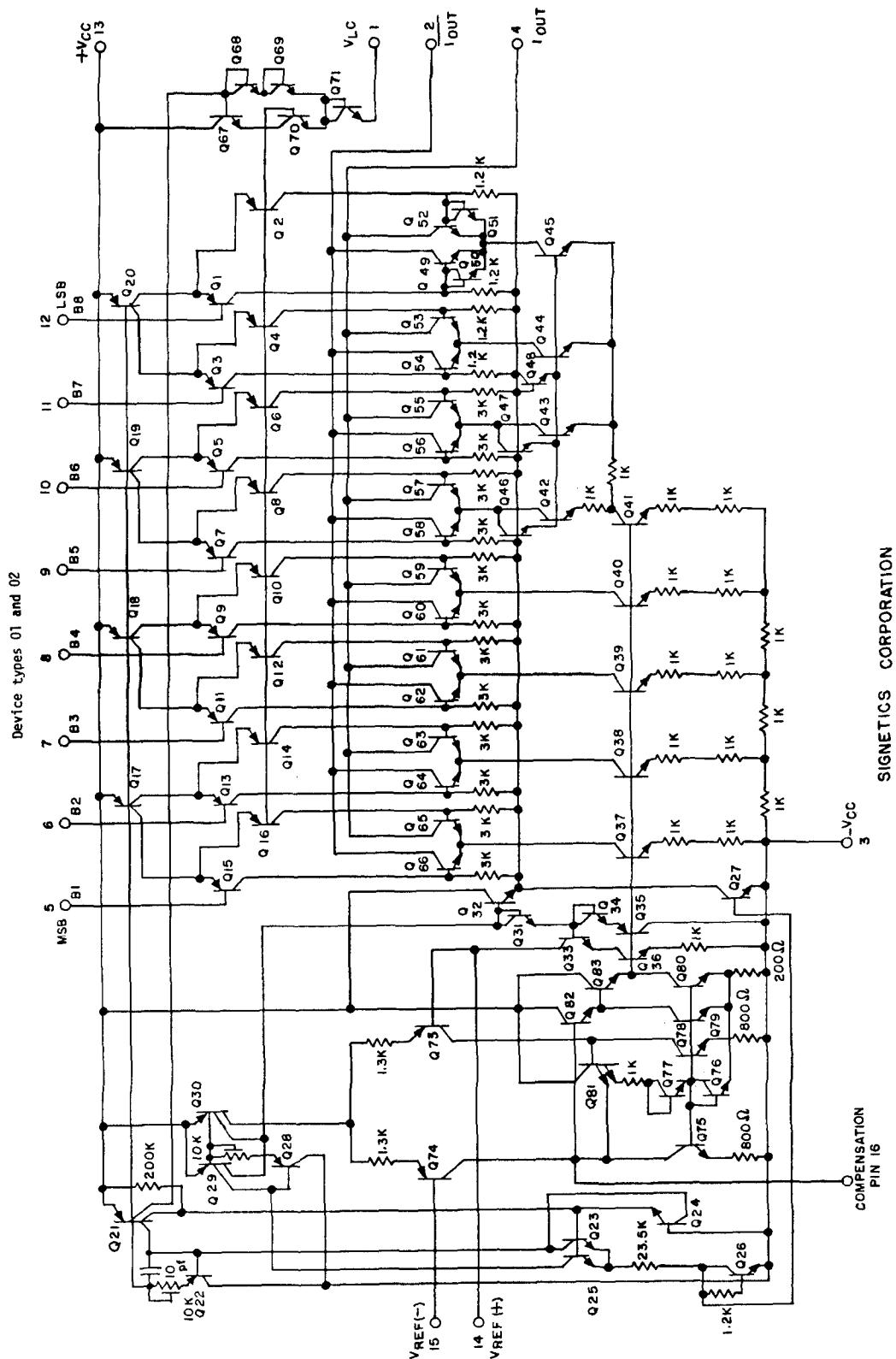
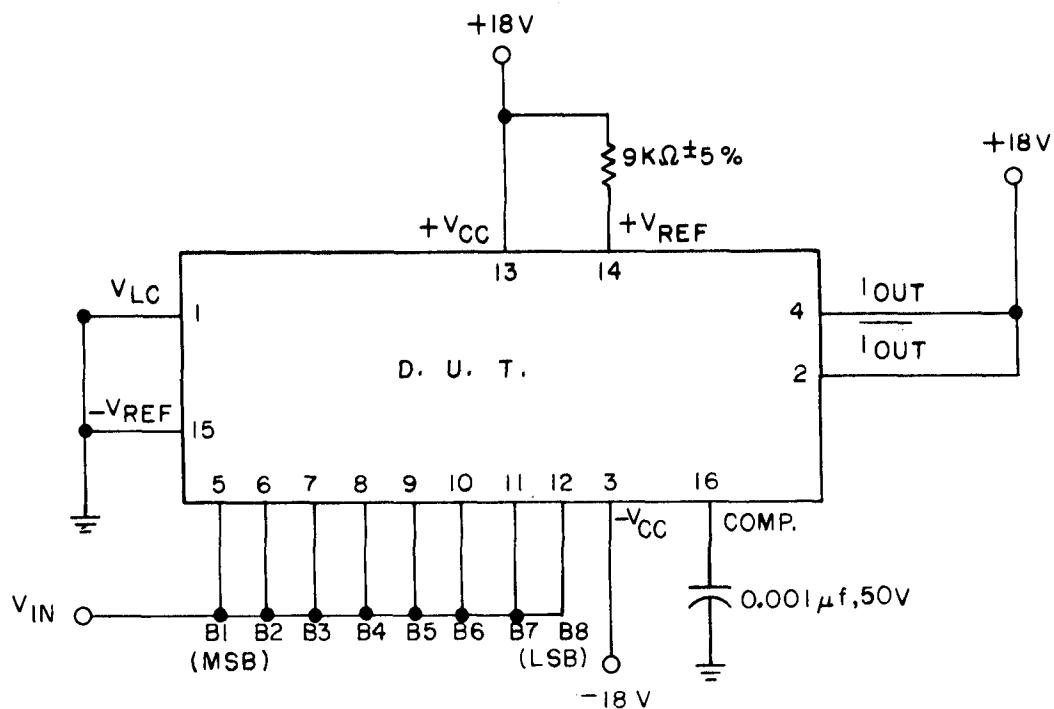


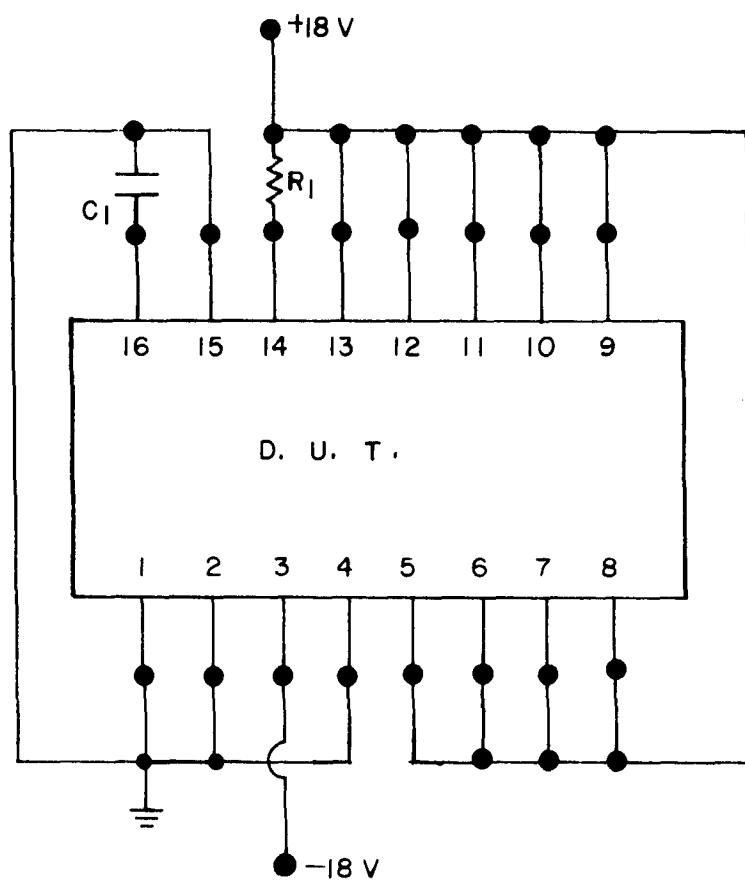
FIGURE 2. Schematic circuits - Continued.



$V_{IN} = 0$ to 3 V square wave
 $\text{@ } 5 \leq f \leq 10 \text{ Hz}$

FIGURE 3. Test circuit, burn-in and operating life test device types 01 and 02.

Device types 01 and 02

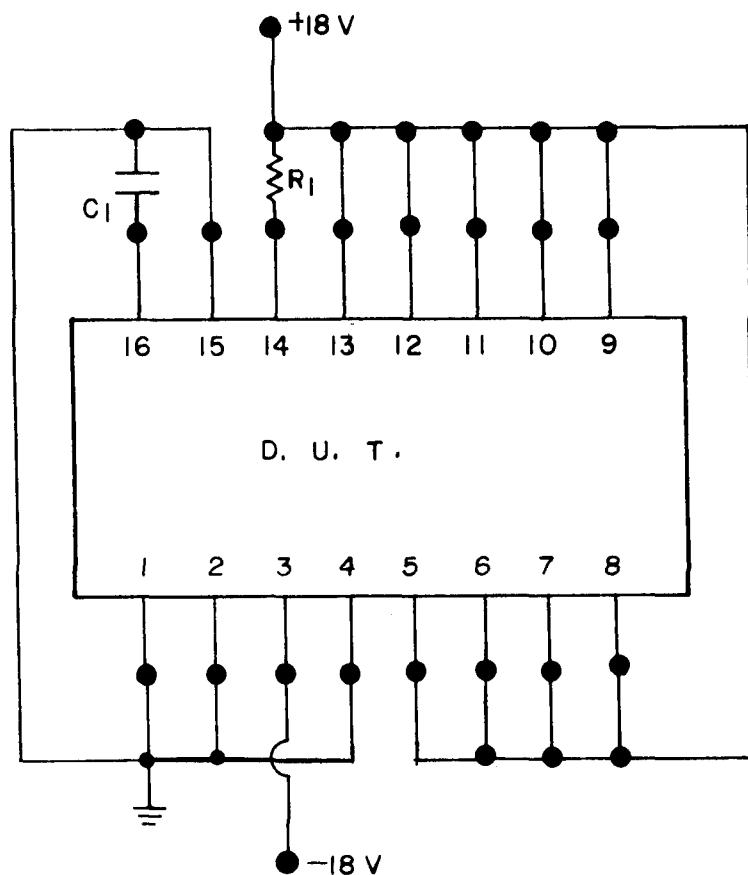


$$R_1 = 9k \pm 5\%$$

$$C_1 = .001 \text{ Mfd}, 50 \text{ V}$$

FIGURE 4. Test circuit, burn-in (steady state power and reverse bias)
and operating life test.

Device types 01 and 02



$$R_1 = 9k \pm 5\%$$
$$C_1 = .001 \text{ Mfd}, 50 \text{ V}$$

FIGURE 5. Test circuit, accelerated burn-in and life test,
device types 01 and 02.

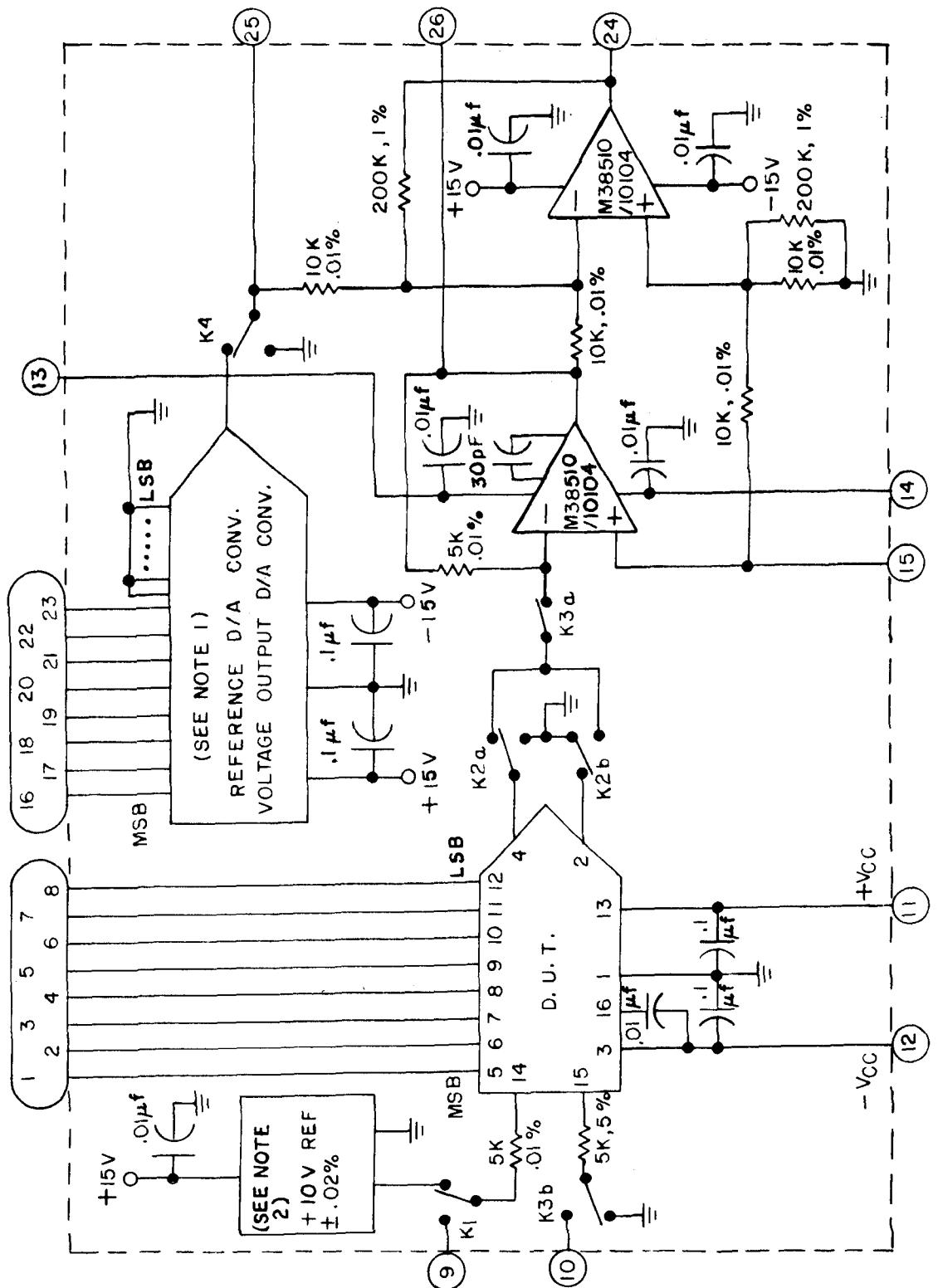


FIGURE 6. Test circuit for static tests.-

NOTES:

1. The reference D/A converter selected should have a resolution of 8 bits or more, and a linearity of 0.015% or better.
2. The voltage reference should have an accuracy of $\pm 0.02\%$ or better.
3. All relays are shown in their unexcited state.

FIGURE 6. Test circuit for static test - Continued.

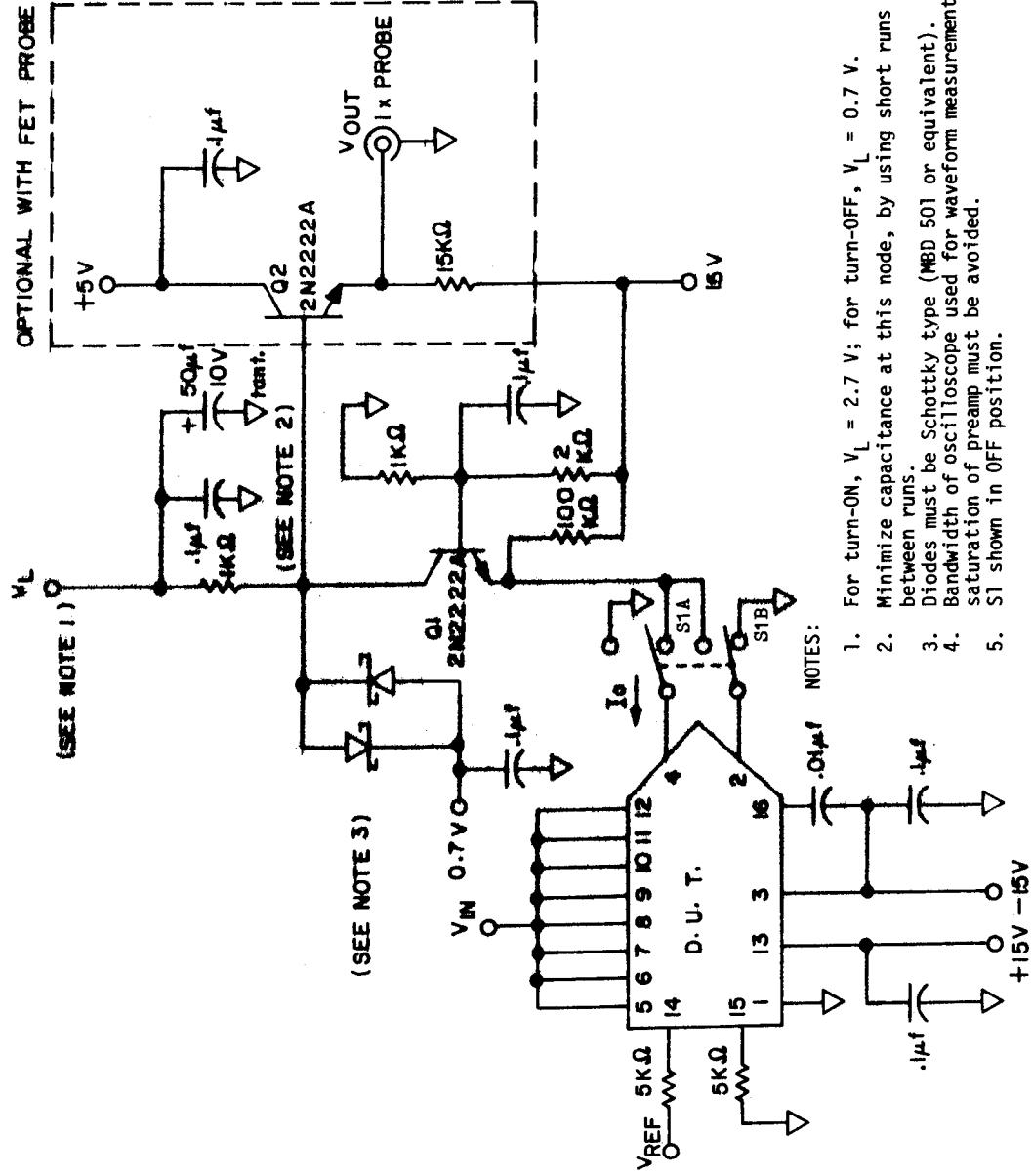


FIGURE 7. Test circuit for propagation delay and settling time, device types 01 and 02.

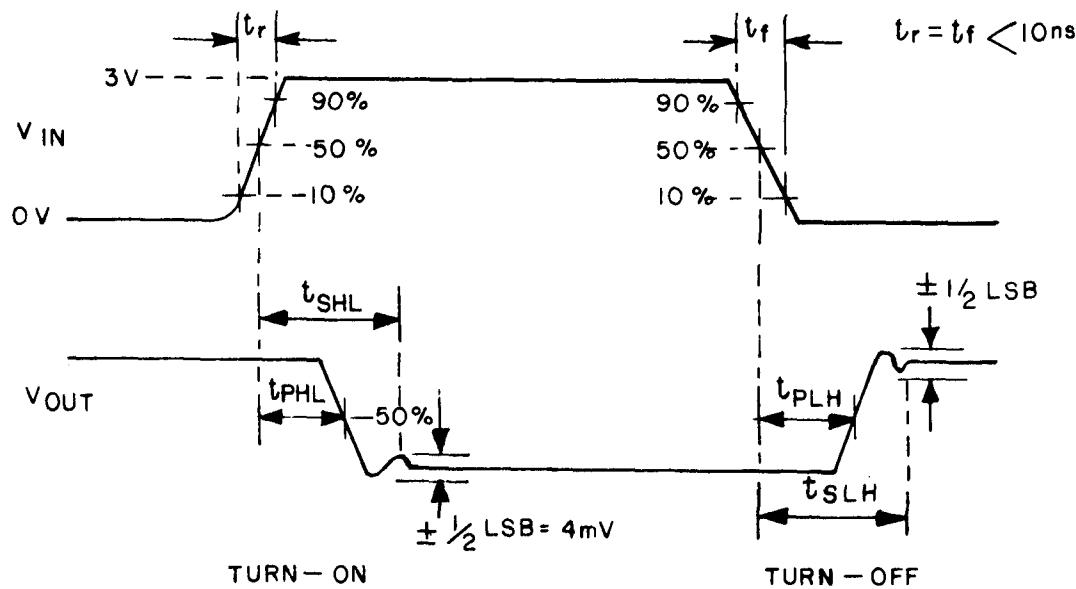


FIGURE 7. Test circuit for propagation delay and settling time, device types 01 and 02 - Continued.

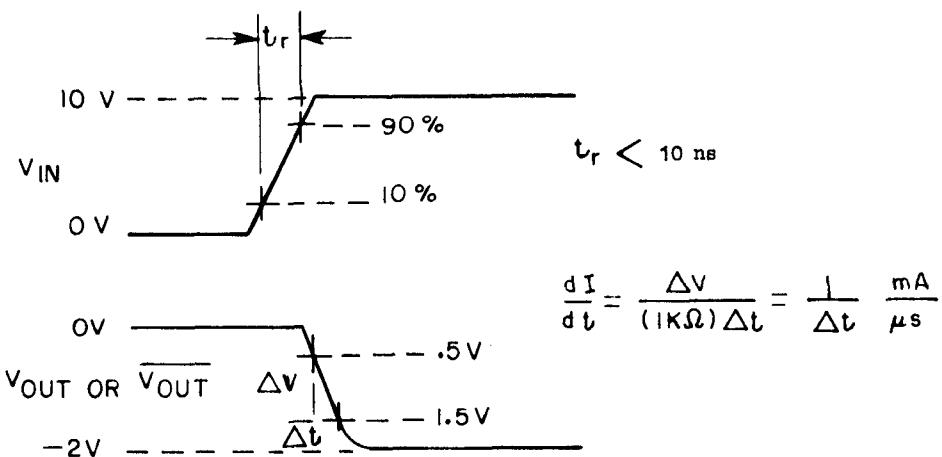
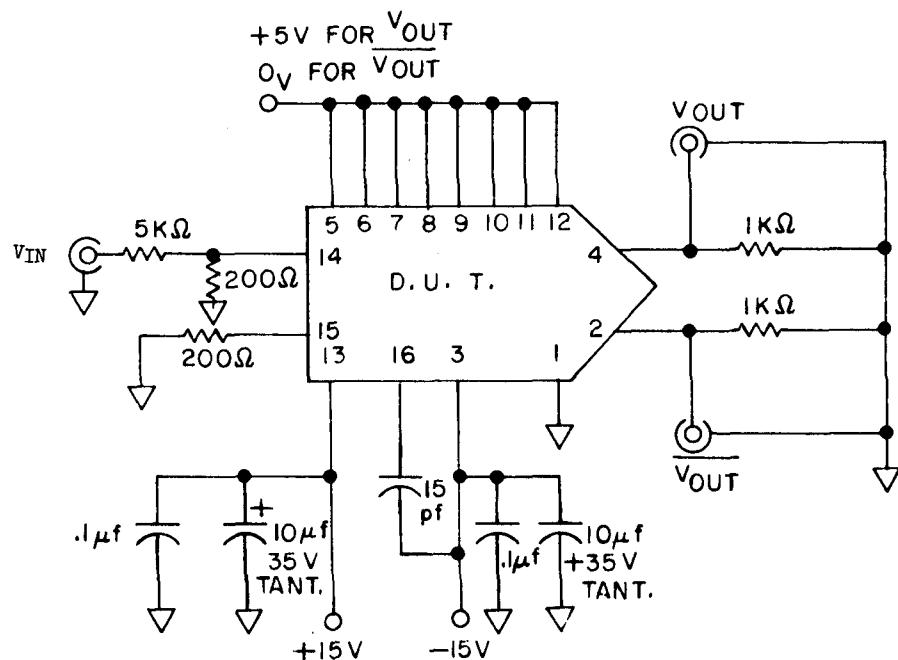
FIGURE 8. Test circuit for slew rate, device types 01, 02.

TABLE III. Group A inspection for device types 01 and 02.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Equation	Measured pin limits				Device 01 Min	Device 01 Max	Device 02 Min	Device 02 Max	Units						
				1 - 8 logic state				9 10 11 12 13 14 15 logic state					16-23 logic state														
				9 v	10 v	11 v	12 v	13 v	14 v	15 v	16-23 logic state		No. energized relays	No. value	Unit												
1 $T_A = 25^\circ C$	I_{CC}^+ I_{CC}^-	3005 3005	1 2	11111111 11111111	+15	-15	+15	-15	0			11 $I_{CC}^+ = I_1$ $I_{CC}^- = I_2$	I_1 mA	0.4	3.8	0.4	3.8	mA									
	I_{FS}	3 1/ 4	00000000 00000000	11111111 11111111						11111111 11111111	K2	24 $I_{FS} = 2-0.01E_1$ $I_{FS} = 2-0.01E_2$	E_1 v	-7.8	-0.8	-7.8	-0.8	mA									
	I_{ZS}	5	00000000								K4	24 $I_{ZS} = -10E_3$ $I_{ZS} = -10E_4$	E_3 v	1.94	2.04	1.984	2.000	mA									
	I_{ZS}	6	11111111								K2, K4	24 $I_{ZS} = -10E_4$	E_4 v	-2.0	2.0	-1.0	1.0	mA									
	$P_{SS}I_{FS}^{+1}$	7	11111111	5.5	-18					11111111	24	E_5 v	$P_{SS}I_{FS}^{+1} = -10(E_5-E_6)$	-4.0	4.0	-4.0	4.0	mA									
	$P_{SS}I_{FS}^{+1}$	8	11111111	4.5	-18					11111111	24	E_6 v	$P_{SS}I_{FS}^{+1} = -10(E_5-E_6)$	-4.0	4.0	-4.0	4.0	mA									
	$P_{SS}I_{FS}^{-1}$	9	00000000	5.5	-18					11111111	K2	24 $P_{SS}I_{FS}^{-1} = -10(E_7-E_8)$	E_7 v	-4.0	4.0	-4.0	4.0	mA									
	$P_{SS}I_{FS}^{-1}$	10	00000000	4.5	-18					11111111	K2	24 $P_{SS}I_{FS}^{-1} = -10(E_7-E_8)$	E_8 v	-4.0	4.0	-4.0	4.0	mA									
	$P_{SS}I_{FS}^{+2}$	11	11111111	18	-18					11111111	24	E_9 v	$P_{SS}I_{FS}^{+2} = -10(E_9-E_{10})$	-8.0	8.0	-8.0	8.0	mA									
	$P_{SS}I_{FS}^{+2}$	12	11111111	12	-18					11111111	24	E_{10} v	$P_{SS}I_{FS}^{+2} = -10(E_9-E_{10})$	-8.0	8.0	-8.0	8.0	mA									
	$P_{SS}I_{FS}^{+2}$	13	00000000	18	-18					11111111	K2	24 $P_{SS}I_{FS}^{+2} = -10(E_{11}-E_{12})$	E_{11} v	-8.0	8.0	-8.0	8.0	mA									
	$P_{SS}I_{FS}^{-1}$	14	00000000	12	-18					11111111	K2	24 $P_{SS}I_{FS}^{-1} = -10(E_{13}-E_9)$	E_{12} v	-8.0	8.0	-8.0	8.0	mA									
	$P_{SS}I_{FS}^{-1}$	15	11111111	18	-12					11111111	K2	24 $P_{SS}I_{FS}^{-1} = -10(E_{14}-E_{11})$	E_{13} v	-8.0	8.0	-8.0	8.0	mA									
	$P_{SS}I_{FS}^{-1}$	16	00000000	18	-12					11111111	K2	24 $P_{SS}I_{FS}^{-1} = -10(E_{14}-E_{11})$	E_{14} v	-8.0	8.0	-8.0	8.0	mA									
	$P_{SS}I_{FS}^{-2}$	17	11111111	18	5.5					11111111	24	E_{15} v	$P_{SS}I_{FS}^{-2} = -10(E_{15}-E_{16})$	-2.0	2.0	-2.0	2.0	mA									
	$P_{SS}I_{FS}^{-2}$	18	11111111	18	4.5					11111111	24	E_{16} v	$P_{SS}I_{FS}^{-2} = -10(E_{15}-E_{16})$	-2.0	2.0	-2.0	2.0	mA									
	$P_{SS}I_{FS}^{-2}$	19	00000000	18	5.5					11111111	K2	24 $P_{SS}I_{FS}^{-2} = -10(E_{17}-E_{18})$	E_{17} v	-2.0	-2.0	-2.0	-2.0	mA									
	$P_{SS}I_{FS}^{-2}$	20	00000000	18	4.5					11111111	K2	24 $P_{SS}I_{FS}^{-2} = -10(E_{17}-E_{18})$	E_{18} v	-2.0	-2.0	-2.0	-2.0	mA									
	I_{FSR_1}	21	11111111	15	15	-10	30	-5		K1, K4	26	E_{19} v	$I_{FSR_1} = 0.2E_{19}$	2.1	---	2.1	---	mA									
	I_{FSR_1}	22	00000000	15	-10	30	-5		K1, K2, K4	26	E_{20} v	$I_{FSR_1} = 0.2E_{20}$	2.1	---	2.1	---	mA										
	I_{FSR_2}	23	11111111	25	-12	30	-5		K1, K4	26	E_{21} v	$I_{FSR_2} = 0.2E_{21}$	4.2	---	4.2	---	mA										
	I_{FSR_2}	24	00000000	25	-12	30	-5		K1, K2, K4	26	E_{22} v	$I_{FSR_2} = 0.2E_{22}$	4.2	---	4.2	---	mA										
	I_{REF}^-	25	00000000	0	-15	15	-15		K3	10	I_3 A	$I_{REF}^- = I_3 \times 10^6$	-3.0	0	-3.0	0	mA										
	I_{IH1}	26 2/ 27 2/	10000000 01000000						1	14	A	$I_{IH1} = I_4 \times 10^6$	-0.01	10.0	-0.01	10.0	mA										
	I_{IH2}	27 2/ 28 2/	00100000 00010000						2	15	A	$I_{IH2} = I_5 \times 10^6$	-0.01	10.0	-0.01	10.0	mA										
	I_{IH3}	28 2/ 29 2/	00010000 00010000						3	16	A	$I_{IH3} = I_6 \times 10^6$	-0.01	10.0	-0.01	10.0	mA										
	I_{IH4}	29 2/ 30 2/	00010000 00010000						4	17	A	$I_{IH4} = I_7 \times 10^6$	-0.01	10.0	-0.01	10.0	mA										

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Adapter pin numbers								Equation	Measured pin No. Value Unit	Device 01 Min Max	Device 02 Min Max	Units	
			1 - 8 logic state	9 V	10 V	11 V	12 V	13 V	14 V	15 V						
$T_A = 25^\circ C$	I _{H5}	30 ^{2/} /000001000	15	-15	15	-15	0				5 I ₈ A	$I_{1H5} = I_8 \times 10^6$	-0.1	10.0	-0.1	10.0
	I _{H6}	31 ^{2/} /00000100									6 I ₉ A	$I_{1H6} = I_9 \times 10^6$	-0.1	10.0	-0.1	10.0
	I _{H7}	32 ^{2/} /00000010									7 I ₁₀ A	$I_{1H7} = I_{10} \times 10^6$	-0.1	10.0	-0.1	10.0
	I _{H8}	33 ^{2/} /00000001									8 I ₁₁ A	$I_{1H8} = I_{11} \times 10^6$	-0.1	10.0	-0.1	10.0
	I _{L1}	34 ^{2/} /10000000									1 I ₁₂ A	$I_{1L1} = I_{12} \times 10^6$	-10.0	-10.0	-10.0	-10.0
	I _{L2}	35 ^{2/} /01000000									2 I ₁₃ A	$I_{1L2} = I_{13} \times 10^6$	-10.0	-10.0	-10.0	-10.0
	I _{L3}	36 ^{2/} /00100000									3 I ₁₄ A	$I_{1L3} = I_{14} \times 10^6$	-10.0	-10.0	-10.0	-10.0
	I _{L4}	37 ^{2/} /00010000									4 I ₁₅ A	$I_{1L4} = I_{15} \times 10^6$	-10.0	-10.0	-10.0	-10.0
	I _{L5}	38 ^{2/} /00001000									5 I ₁₆ A	$I_{1L5} = I_{16} \times 10^6$	-10.0	-10.0	-10.0	-10.0
	I _{L6}	39 ^{2/} /00000100									6 I ₁₇ A	$I_{1L6} = I_{17} \times 10^6$	-10.0	-10.0	-10.0	-10.0
V_{CAL}	I _{L7}	40 ^{2/} /00000010									7 I ₁₈ A	$I_{1L7} = I_{18} \times 10^6$	-10.0	-10.0	-10.0	-10.0
	I _{L8}	41 ^{2/} /00000001									8 I ₁₉ A	$I_{1L8} = I_{19} \times 10^6$	-10.0	-10.0	-10.0	-10.0
	V _{CAL1}	42									24 E ₂₃ V	$V_{CAL1} = E_{23}$	-	-	-	-
	I _{FS} ⁺	43	11111111	15	-15	30	0	18	11111111		24 E ₂₄ V	$I_{FS}^+ = 2.0 \cdot 0.01(E_{24} - E_{23})$	1.94	2.04	1.90	2.08
	I _{FS} ⁻	44	00000000			30	0	18	11111111	K2	24 E ₂₅ V	$\overline{I_{FS}}^+ = 2.0 \cdot 0.01(E_{25} - E_{23})$	1.94	2.04	1.90	2.08
	V _{CAL2}	45	11111111	15	-15	-10	11111111			24 E ₂₆ V	$V_{CAL2} = E_{26}$	-	-	-	-	
	I _{FS} ⁻	46	11111111	15	-15	-10	11111111			24 E ₂₇ V	$I_{FS}^- = 2.0 \cdot 0.01(E_{27} - E_{26})$	1.94	2.04	1.90	2.08	
	I _{FS} ⁻	47	00000000			15	-15	-10	11111111	K2	24 E ₂₈ V	$\overline{I_{FS}}^- = 2.0 \cdot 0.01(E_{28} - E_{26})$	1.94	2.04	1.90	2.08
	ΔI_{FSC}	48									$A_{1FSC} = 1000(1_{FS}^+ + 1_{FS}^-)$	-4.0	4.0	-4.0	4.0	
	ΔI_{FSC}	49									$\Delta T_{FSC} = 1000(T_{FS}^+ - T_{FS}^-)$	-4.0	4.0	-4.0	4.0	
V_{CAL3}	50	00000000	15	-15	15	-15	0	00000000		24 E ₂₉ V	$V_{CAL3} = E_{29}$	-	-	-	-	
	V _{CAL4}	51	11111111					11111111		24 E ₃₀ V	$V_{CAL4} = E_{30}$	-	-	-	-	
	V _{CAL5}	52	11111111					11111111	K2	24 E ₃₁ V	$V_{CAL5} = E_{31}$	-	-	-	-	
	V _{CAL6}	53	00000000					00000000	K2	24 E ₃₂ V	$V_{CAL6} = E_{32}$	-	-	-	-	
	NL ₁	54	10000000								$NL_1 = \frac{(E_{33} - V_{CAL3})}{I_{FS} \times 10^3} - \frac{(128)(V_{CAL4} - V_{CAL3})}{(255)I_{FS} \times 10^3}$	-	-	-	-	
															%	

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Measured pin No.	Unit	Equation	Device 01 Min	Device 01 Max	Device 02 Min	Device 02 Max	Units	
				1 - 8 logic state	9 v	10 v	11 v	12 v	13 v	14 v	15 v									
1 $T_A = 25^\circ C$	NL ₂		55	01000000	15	-15	15	-15	0	01000000		24	E_{34}	v	$NL_2 = \frac{(E_{34}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(64)(V_{CAL4}-V_{CAL3})}{(255) I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₃		56	00100000						00100000		24	E_{35}	v	$NL_3 = \frac{(E_{35}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(32)(V_{CAL4}-V_{CAL3})}{(255) I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₄		57	00010000						00010000		24	E_{36}	v	$NL_4 = \frac{(E_{36}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(16)(V_{CAL4}-V_{CAL3})}{(255) I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₅		58	00001000						00001000		24	E_{37}	v	$NL_5 = \frac{(E_{37}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(8)(V_{CAL4}-V_{CAL3})}{(255) I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₆		59	00000100						00000100		24	E_{38}	v	$NL_6 = \frac{(E_{38}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(4)(V_{CAL4}-V_{CAL3})}{(255) I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₇		60	00000010						00000010		24	E_{39}	v	$NL_7 = \frac{(E_{39}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(12)(V_{CAL4}-V_{CAL3})}{(255) I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₈		61	00000001						00000001		24	E_{40}	v	$NL_8 = \frac{(E_{40}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(1)(V_{CAL4}-V_{CAL3})}{(255) I_{FS} \times 10^3}$	—	—	—	—	%

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Measured pin No.	Unit	Equation	Limits		Device 01 Min	Device 02 Min	Device 01 Max	Device 02 Max	Units
				1	8	9	10	11	12	13	14				Min	Max					
$T_A = 25^\circ C$	\overline{NL}_1	62	01111111		15	-15	15	-15	0	10000000		24	E_{41}	V	$\overline{NL}_1 = \frac{(E_{41}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(128)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	\overline{NL}_2	63	10111111							01000000		24	E_{42}	V	$\overline{NL}_2 = \frac{(E_{42}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(64)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	\overline{NL}_3	64	11011111							00100000		24	E_{43}	V	$\overline{NL}_3 = \frac{(E_{43}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(32)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	\overline{NL}_4	65	11101111							00010000		24	E_{44}	V	$\overline{NL}_4 = \frac{(E_{44}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(16)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	\overline{NL}_5	66	11110111							00001000		24	E_{45}	V	$\overline{NL}_5 = \frac{(E_{45}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(8)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	\overline{NL}_6	67	11111011							00000100		24	E_{46}	V	$\overline{NL}_6 = \frac{(E_{46}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(4)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	\overline{NL}_7	68	11111101							00000010		24	E_{47}	V	$\overline{NL}_7 = \frac{(E_{47}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(2)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test logic state no.	Adapter pin numbers								Measured pin No.	Equation	Limits		Device 02 Min	Device 02 Max	Units			
				1	-8	9	10	11	12	13	14	15		Min	Max						
$T_A = 25^\circ C$	\overline{NL}_3		69	11111110		15	-15	15	-15	0	00000001		24	E_{48}	V	$\overline{NL}_3 = \frac{(E_{48}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	%	
	ZNL^+		70													$\Delta N_{NL}^+ = NL_{-1} + NL_K + \dots$ (1, k = bits having positive errors)	0	0.19	0	0.10	%
	\overline{NL}^+		71													$\Delta N_{NL}^+ = NL_{-1} + NL_K + \dots$	0	0.19	0	0.10	%
	ZNL^-		72													$\Delta N_{NL}^- = NL_m + NL_n + \dots$ (m, n = bits having negative errors)	-0.19	0	-0.10	0	%
	\overline{NL}^-		73													$\Delta N_{NL}^- = NL_m + NL_n + \dots$	-0.19	0	-0.10	0	%
	ΔZNL		74													$\Delta ZNL = ZNL^+ - ZNL^- $	-0.05	0.05	-0.03	0.03	%
	$\Delta \overline{NL}$		75													$\Delta \overline{NL} = ZNL^+ - ZNL^- $	-0.05	0.05	-0.03	0.03	%
	NL^+		76													$NL^+ = ZNL^+ + \Delta ZNL $	0	0.19	0	0.10	%
	\overline{NL}^+		77													$\overline{NL}^+ = ZNL^+ + \Delta \overline{NL} $	0	0.19	0	0.10	%
	NL^-		78													$NL^- = ZNL^- + \Delta ZNL $	0	0.19	0	0.10	%
	\overline{NL}^-		79													$\overline{NL}^- = ZNL^- + \Delta \overline{NL} $	0	0.19	0	0.10	%
$T_A = 0^\circ C$	$(I_{01})_a$		80	10000000	15	-15	15	-15	0	10000000		24	E_{49}	V	$(I_{01})_a = I_{FS} \times \frac{128}{255} - 0.01(E_{49})$	-	-	-	-	mA	
	$(I_{01})_b$		81	01111111	15	-15	15	-15	0	01111111		24	E_{50}	V	$(I_{01})_b = I_{FS} \times \frac{127}{255} - 0.01(E_{50})$	-	-	-	-	mA	
	$\Delta(I_{01})$		82													$\Delta(I_{01}) = [(I_{01})_a - (I_{01})_b] \times 10^3$	0	0.19	0	0.10	%
	$(I_{02})_a$		83	01000000	15	-15	15	-15	0	01000000		24	E_{51}	V	$(I_{02})_a = I_{FS} \times \frac{64}{255} - 0.01(E_{51})$	-	-	-	-	mA	
	$(I_{02})_b$		84	00111111	15	-15	15	-15	0	00111111		24	E_{52}	V	$(I_{02})_b = I_{FS} \times \frac{63}{255} - 0.01(E_{52})$	-	-	-	-	mA	
	$\Delta(I_{02})$		85													$\Delta(I_{02}) = [(I_{02})_a - (I_{02})_b] \times 10^3$	0	0.19	0	0.10	%
	$(I_{03})_a$		86	00100000	15	-15	15	-15	0	00100000		24	E_{53}	V	$(I_{03})_a = I_{FS} \times \frac{32}{255} - 0.01(E_{53})$	-	-	-	-	mA	
	$(I_{03})_b$		87	00011111	15	-15	15	-15	0	00011111		24	E_{54}	V	$(I_{03})_b = I_{FS} \times \frac{31}{255} - 0.01(E_{54})$	-	-	-	-	mA	
	$\Delta(I_{03})$		88													$\Delta(I_{03}) = [(I_{03})_a - (I_{03})_b] \times 10^3$	0	0.19	0	0.10	mA

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-853 method	Master pin numbers										Equation		Device 01		Device 02		Units		
			1 - 8 logic state					9 - 16 logic state					Energized relays		No.	Measured pin value	Unit				
			Test no.	v	v	v	v	v	v	v	v	v	v	v	v	v	v	v			
$T_A = 25^\circ C$	$(I_{04})_a$	89	00010000	15	-15	15	-15	0	00010000				24	E_{55}	V	$(I_{04})_a = I_{FS} \times \frac{16}{255} - 0.01(E_{55})$	-	-	-	mA	
	$(I_{04})_b$	90	00001111	15	-15	15	-15	0	00001111				24	E_{56}	V	$(I_{04})_b = I_{FS} \times \frac{15}{255} - 0.01(E_{56})$	-	-	-	mA	
	ΔI_{04}	91														$\Delta I_{04} = [(I_{04})_a - (I_{04})_b] \times 10^3$	0	16.0	0	16.0	μA
	$(I_{05})_a$	92	00001000	15	-15	15	-15	0	00001000				24	E_{57}	V	$(I_{05})_a = I_{FS} \times \frac{8}{255} - 0.01(E_{57})$	-	-	-	mA	
	$(I_{05})_b$	93	00000111	15	-15	15	-15	0	00000111				24	E_{58}	V	$(I_{05})_b = I_{FS} \times \frac{7}{255} - 0.01(E_{58})$	-	-	-	mA	
	ΔI_{05}	94														$\Delta I_{05} = [(I_{05})_a - (I_{05})_b] \times 10^3$	0	16.0	0	16.0	μA
	$(I_{06})_a$	95	00000100	15	-15	15	-15	0	00000100				24	E_{59}	V	$(I_{06})_a = I_{FS} \times \frac{4}{255} - 0.01(E_{59})$	-	-	-	mA	
	$(I_{06})_b$	96	00000011	15	-15	15	-15	0	00000011				24	E_{60}	V	$(I_{06})_b = I_{FS} \times \frac{3}{255} - 0.01(E_{60})$	-	-	-	mA	
	ΔI_{06}	97														$\Delta I_{06} = [(I_{06})_a - (I_{06})_b] \times 10^3$	0	16.0	0	16.0	μA
	$(I_{07})_a$	98	00000010	15	-15	15	-15	0	00000010				24	E_{61}	V	$(I_{07})_a = I_{FS} \times \frac{2}{255} - 0.01(E_{61})$	-	-	-	mA	
	$(I_{07})_b$	99	00000001	15	-15	15	-15	0	00000001				24	E_{62}	V	$(I_{07})_b = I_{FS} \times \frac{1}{255} - 0.01(E_{62})$	-	-	-	mA	
	ΔI_{07}	100														$\Delta I_{07} = [(I_{07})_a - (I_{07})_b] \times 10^3$	0	16.0	0	16.0	μA
	$(I_{08})_a$	101	00000000	15	-15	15	-15	0	00000000				24	E_{63}	V	$(I_{08})_a = I_{FS} \times \frac{1}{255} - 0.01(E_{63})$	-	-	-	mA	
	ΔI_{08}	102														$\Delta I_{08} = [(I_{08})_a - (I_{08})_b] \times 10^3$	0	16.0	0	16.0	μA
	ΔI_{FS}	103														$I_{FS} - \overline{I_{FS}} = \Delta I_{FS}$	-8.0	8.0	-4.0	4.0	μA
$T_A = 125^\circ C$	I_{CC}^+	3005	104	11111111	+15	-15	+15	-15	0			11	I_{20}	mA	$I_{CC}^+ = I_{20}$	0.4	3.8	0.4	3.8	mA	
	I_{CC}^-	3005	105	11111111								12	I_{21}	mA	$I_{CC}^- = I_{21}$	-7.8	-0.8	-7.8	-0.8	mA	
	I_{FS}	106	11111111							11111111			24	E_{64}	V	$I_{FS} = 2 - 0.01E_{64}$	1.94	2.04	1.984	2.000	mA
	$\overline{I_{FS}}$	107	00000000							11111111			24	E_{65}	V	$\overline{I_{FS}} = 2 - 0.01E_{65}$	1.94	2.04	1.984	2.000	mA
	I_{ZS}	108	00000000										24	E_{66}	V	$I_{ZS} = -10E_{66}$	-2.0	2.0	-1.0	1.0	μA
	$\overline{I_{ZS}}$	109	11111111										24	E_{67}	V	$\overline{I_{ZS}} = -10E_{67}$	-2.0	2.0	-1.0	1.0	μA
	$P_{SS}I_{FS+1}$	110	11111111							11111111			24	E_{68}	V	$P_{SS}I_{FS+1} = -10(E_{68} - E_{69})$	-4.0	4.0	-4.0	4.0	μA
		111	11111111							11111111			24	E_{69}	V						

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Adapter pin numbers												Equation			Limits								
			1 - 8 logic state						9 - 16 logic state						16-23 logic state		Energized relays		Measured pin No.	Value	Unit	Device 01		Device 02		Units
			1	2	3	4	5	6	9	10	11	12	13	14	15	16	17	18	19	20	E ₇₀	V	E ₇₁	V	P _{SS} I _{FS} ⁻¹ = -10(E ₇₀ -E ₇₁)	-4.0
$T_A = 125^\circ C$	P _{SS} I _{FS} ⁺¹		112	00000000		5.5	-18	+15	-15	0	11111111	K2	24	E ₇₀	V	P _{SS} I _{FS} ⁺¹ = -10(E ₇₀ -E ₇₁)	-4.0	4.0	-4.0	4.0	μA					
	P _{SS} I _{FS} ⁺²		113	00000000		4.5	-18				11111111	K2	24	E ₇₁	V	P _{SS} I _{FS} ⁺² = -10(E ₇₂ -E ₇₃)	-3.0	8.0	-8.0	8.0	μA					
	P _{SS} I _{FS} ⁺²		114	11111111		18	-18				11111111		24	E ₇₂	V	P _{SS} I _{FS} ⁺² = -10(E ₇₂ -E ₇₃)	-3.0	8.0	-8.0	8.0	μA					
	P _{SS} I _{FS} ⁻¹		115	11111111		12	-18				11111111		24	E ₇₃	V	P _{SS} I _{FS} ⁻² = -10(E ₇₄ -E ₇₅)	-3.0	8.0	-8.0	8.0	μA					
	P _{SS} I _{FS} ⁻¹		116	00000000		18	-18				11111111	K2	24	E ₇₄	V	P _{SS} I _{FS} ⁻² = -10(E ₇₄ -E ₇₅)	-3.0	8.0	-8.0	8.0	μA					
	P _{SS} I _{FS} ⁻¹		117	00000000		12	-18				11111111	K2	24	E ₇₅	V	P _{SS} I _{FS} ⁻² = -10(E ₇₄ -E ₇₅)	-3.0	8.0	-8.0	8.0	μA					
	P _{SS} I _{FS} ⁻¹		118	11111111		18	-12				11111111		24	E ₇₆	V	P _{SS} I _{FS} ⁻¹ = -10(E ₆ -E ₇₂)	-8.0	8.0	-8.0	8.0	μA					
	P _{SS} I _{FS} ⁻¹		119	00000000		18	-12				11111111	K2	24	E ₇₇	V	P _{SS} I _{FS} ⁻¹ = -10(E ₇₇ -E ₇₄)	-8.0	8.0	-8.0	8.0	μA					
	P _{SS} I _{FS} ⁻²		120	11111111		18	5.5				11111111		24	E ₇₈	V	P _{SS} I _{FS} ⁻² = -10(E ₁₈ -E ₇₉)	-2.0	2.0	-2.0	2.0	μA					
	P _{SS} I _{FS} ⁻²		121	11111111		18	4.5				11111111		24	E ₇₉	V	P _{SS} I _{FS} ⁻² = -10(E ₁₈ -E ₇₉)	-2.0	2.0	-2.0	2.0	μA					
$T_A = 25^\circ C$	P _{SS} I _{FS} ⁻¹		122	00000000		18	5.5				11111111	K2	24	E ₈₀	V	P _{SS} I _{FS} ⁻² = -10(E ₈₀ -E ₈₁)	-2.0	2.0	-2.0	2.0	μA					
	P _{SS} I _{FS} ⁻¹		123	00000000		18	4.5				11111111	K2	24	E ₈₁	V	P _{SS} I _{FS} ⁻² = -10(E ₈₀ -E ₈₁)	-2.0	2.0	-2.0	2.0	μA					
	I _{FS} ^{R1}		124	11111111	15	15	-10	30	-5		K1,K4	26	E ₈₂	V	I _{FS} R ₁ = 0.2E ₈₂	2.1		2.1		mA						
	I _{FS} ^{R1}		125	00000000	15		-10	30	-5		K1,K2,K4	26	E ₈₃	V	I _{FS} R ₁ = 0.2E ₈₃	2.1		2.1		mA						
	I _{FS} ^{R2}		126	11111111	25		-12	30	-5		K1,K4	26	E ₈₄	V	I _{FS} R ₂ = 0.2E ₈₄	4.2		4.2		mA						
	I _{FS} ^{R2}		127	00000000	25		-12	30	-5		K1,K2,K4	26	E ₈₅	V	I _{FS} R ₂ = 0.2E ₈₅	4.2		4.2		mA						
	I _{REF} ⁻		128	00000000	0		-15	15	-15		K3	10	I ₂₂	A	I _{REF} ⁻ = I ₂₂ X 10 ⁶	-3.0	0	-3.0	0							
	I _{TH1}		129 ^{2/}	10000000							1	I ₂₃	A	I _{TH1} = I ₂₃ X 10 ⁶	-0.01	10.0	-0.01	10.0	μA							
	I _{TH2}		130 ^{2/}	01000000							2	I ₂₄	A	I _{TH2} = I ₂₄ X 10 ⁶	-0.01	10.0	-0.01	10.0	μA							
	I _{TH3}		131 ^{2/}	00100000							3	I ₂₅	A	I _{TH3} = I ₂₅ X 10 ⁶	-0.01	10.0	-0.01	10.0	μA							
	I _{TH4}		132 ^{2/}	00010000							4	I ₂₆	A	I _{TH4} = I ₂₆ X 10 ⁶	-0.01	10.0	-0.01	10.0	μA							
	I _{TH5}		133 ^{2/}	00001000							5	I ₂₇	A	I _{TH5} = I ₂₇ X 10 ⁶	-0.01	10.0	-0.01	10.0	μA							
	I _{TH6}		134 ^{2/}	00000100							6	I ₂₈	A	I _{TH6} = I ₂₈ X 10 ⁶	-0.01	10.0	-0.01	10.0	μA							
	I _{IL1}		135 ^{2/}	00000010							7	I ₂₉	A	I _{IL1} = I ₂₉ X 10 ⁶	-0.01	10.0	-0.01	10.0	μA							
	I _{IL2}		136 ^{2/}	00000001							8	I ₃₀	A	I _{IL2} = I ₃₀ X 10 ⁶	-0.01	10.0	-0.01	10.0	μA							
	I _{IL3}		137 ^{2/}	10000000							1	I ₃₁	A	I _{IL1} = I ₃₁ X 10 ⁶	-10.0		-10.0		μA							
	I _{IL4}		138 ^{2/}	01000000							2	I ₃₂	A	I _{IL2} = I ₃₂ X 10 ⁶	-10.0		-10.0		μA							
	I _{IL5}		139 ^{2/}	00100000							3	I ₃₃	A	I _{IL3} = I ₃₃ X 10 ⁶	-10.0		-10.0		μA							
	I _{IL6}		140 ^{2/}	00010000							4	I ₃₄	A	I _{IL4} = I ₃₄ X 10 ⁶	-10.0		-10.0		μA							
	I _{IL7}		141 ^{2/}	00001000							5	I ₃₅	A	I _{IL5} = I ₃₅ X 10 ⁶	-10.0		-10.0		μA							

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Adapter pin numbers								Measured pin No.	Value	Unit	Limits				
			1 - 8	Test logic state no.	9	10	11	12	13	14	15			Device 01 Min	Device 01 Max	Device 02 Min	Device 02 Max	
$T_A = 125^\circ C$	I _{IL6}	142 ^{2/}	00000100		15	-15	15	-15	0			6	I ₃₆	A	I _{IL6} = 136×10^6	-10.0	-10.0	μA
	I _{IL7}	143 ^{2/}	00000010		15	-15	15	-15	0			7	I ₃₇	A	I _{IL7} = 137×10^6	-10.0	-10.0	μA
	I _{IL8}	144 ^{2/}	00000001		15	-15	15	-15	0			8	I ₃₈	A	I _{IL8} = 138×10^6	-10.0	-10.0	μA
	V _{CAL1}	145										24	E ₈₆	V	V _{CAL1} = E ₈₆			V
	I _{FS+}	146	11111111		15	-15	30	0	18	11111111		24	E ₈₇	V	I _{FS+} = $2 - 0.01(E_{97} - E_{96})$	1.94	2.04	μA
	I _{FS-}	147	00000000		15	-15	30	0	18	11111111	K2	24	E ₈₈	V	I _{FS-} = $2 - 0.01(E_{98} - E_{96})$	1.94	2.04	μA
V_{CAL2}	V _{CAL2}	148	11111111		15	-15	15	-15	-10	11111111		24	E ₈₉	V	V _{CAL2} = E ₈₉			V
	I _{FS-}	149	11111111		15	-15	15	-15	-10	11111111		24	E ₉₀	V	I _{FS-} = $2 - 0.01(E_{90} - E_{89})$	1.94	2.04	μA
	I _{FS-}	150	00000000		15	-15	15	-15	-10	11111111	K2	24	E ₉₁	V	I _{FS-} = $2 - 0.01(E_{91} - E_{89})$	1.94	2.04	μA
	ΔI_{FSC}	151													$\Delta I_{FSC} = 1000 (I_{FS+} - I_{FS-})$	-4.0	4.0	μA
	ΔI_{FSC}	152													$\Delta I_{FSC} = 1000 (I_{FS+} - I_{FS-})$	-4.0	4.0	μA
	V _{CAL3}	153	00000000		15	-15	15	-15	0	00000000		24	E ₉₂	V	V _{CAL3} = E ₉₂			V
V_{CAL4}	V _{CAL4}	154	11111111							11111111		24	E ₉₃	V	V _{CAL4} = E ₉₃			V
	V _{CAL5}	155	11111111							11111111	K2	24	E ₉₄	V	V _{CAL5} = E ₉₄			V
	V _{CAL6}	156	00000000							00000000	K2	24	E ₉₅	V	V _{CAL6} = E ₉₅			V
	NL ₁	157	10000000							10000000		24	E ₉₆	V	$NL_1 = \frac{(E_{96} - V_{CAL3})}{I_{FS} \times 10^3} - \frac{(128)(V_{CAL4} - V_{CAL3})}{255 I_{FS} \times 10^3}$			%
	NL ₂	158	01000000							01000000		24	E ₉₇	V	$NL_2 = \frac{(E_{97} - V_{CAL3})}{I_{FS} \times 10^3} - \frac{(64)(V_{CAL4} - V_{CAL3})}{255 I_{FS} \times 10^3}$			%
	NL ₃	159	00100000							00100000		24	E ₉₈	V	$NL_3 = \frac{(E_{98} - V_{CAL3})}{I_{FS} \times 10^3} - \frac{(32)(V_{CAL4} - V_{CAL3})}{255 I_{FS} \times 10^3}$			%

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Energized relays	Measured pin No.	Unit	Equation	Device 01 Min	Device 01 Max	Device 02 Min	Device 02 Max	
				1 - 8 logic state	9 v	10 v	11 v	12 v	13 v	14 v	15 v									
$T_A = 125^\circ C$	NL ₄		160	000010000		15	-15	15	-15	0	000010000		24	E_{99} v		$NL_4 = \frac{(E_{99}-V_{CAL3})}{I_{FS} \times 10^3} -$				
	NL ₅		161	00001000							000001000		24	E_{100} v		$NL_5 = \frac{(E_{100}-V_{CAL3})}{I_{FS} \times 10^3} -$				
	NL ₆		162	00000100							000000100		24	E_{101} v		$NL_6 = \frac{(E_{101}-V_{CAL3})}{I_{FS} \times 10^3} -$				
	NL ₇		163	00000010							000000010		24	E_{102} v		$NL_7 = \frac{(E_{102}-V_{CAL3})}{I_{FS} \times 10^3} -$				
	NL ₈		164	00000001							000000001		24	E_{103} v		$NL_8 = \frac{(E_{103}-V_{CAL3})}{I_{FS} \times 10^3} -$				
	NL ₁		165	01111111							10000000		24	E_{104} v		$NL_1 = \frac{(E_{104}-V_{CAL5})}{I_{FS} \times 10^3} -$				
	NL ₂		166	10111111							01000000		24	E_{105} v		$NL_2 = \frac{(E_{105}-V_{CAL5})}{I_{FS} \times 10^3} -$				

See footnotes at end of table.

TABLE III. Group A Inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Measured pin No.	Equation	Units		
				1 - 8 logic state	9 v	10 v	11 v	12 v	13 v	14 v	15 v					
$T_A = 2^2$ °C	\overline{NL}_3		167	11011111				15	-15	15	-15	0	00100000	24	$E_{106} - V_{CAL5}$	$I_{FS} \times 10^3$
																$(\frac{32}{255}) (V_{CAL6} - V_{CAL5})$
	\overline{NL}_4		168	11101111									000010000	24	$E_{107} - V_{CAL5}$	$I_{FS} \times 10^3$
																$(\frac{16}{255}) (V_{CAL6} - V_{CAL5})$
	\overline{NL}_5		169	11110111									000001000	24	$E_{108} - V_{CAL5}$	$I_{FS} \times 10^3$
																$(\frac{8}{255}) (V_{CAL6} - V_{CAL5})$
	\overline{NL}_6		170	11111011									000000100	24	$E_{109} - V_{CAL5}$	$I_{FS} \times 10^3$
																$(\frac{4}{255}) (V_{CAL6} - V_{CAL5})$
	\overline{NL}_7		171	11111101									000000010	24	$E_{110} - V_{CAL5}$	$I_{FS} \times 10^3$
																$(\frac{2}{255}) (V_{CAL6} - V_{CAL5})$
	\overline{NL}_8		172	11111110									000000001	24	$E_{111} - V_{CAL5}$	$I_{FS} \times 10^3$
	ΣNL^+		173													$(\Sigma NL_i^+ + NL_k^+ + \dots)$
	ΣNL^-		174													$(NL_i^- + NL_k^- + \dots)$

See footnotes at end of table.

TABLE IIII. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Energized relays	Measured pin unit	Equation		Limits		Units	
				1 - 8 logic state	9 V	10 V	11 V	12 V	13 V	14 V	15 V			No. Value	Device 01 Min	Device 01 Max	Device 02 Min	Device 02 Max	
2	ΣNL^-	$T_A = 125^\circ C$	175											$\Delta NL^- = NL_m + NL_n + \dots$ ($m, n =$ bits having negative errors)	-0.19	0	-0.10	0	%
	ΣNL^-		176											$\Delta NL^- = NL_m' + NL_n' + \dots$	-0.19	0	-0.10	0	%
	ΔNL		177											$\Delta NL = NL^+ - NL^- $	-0.05	0.05	-0.03	0.03	%
	ΔNL		178											$\Delta NL = NL^+ - NL^- $	-0.05	0.05	-0.03	0.03	%
	NL^+		179											$NL^+ = NL^+ + \Delta NL $	0	0.19	0	0.10	%
	NL^+		180											$NL^+ = NL^+ + \Delta NL $	0	0.19	0	0.10	%
	NL^-		181											$NL^- = NL^- + \Delta NL $	0	0.19	0	0.10	%
	NL^-		182											$NL^- = NL^- + \Delta NL $	0	0.19	0	0.10	%
	$(I_{01})_a$		183	10000000	15	-15	0	10000000	24	E_{112}	V	$(I_{01})_a = I_{FS} \times \frac{128}{255} - 0.01(E_{112})$	—	—	—	—	mA		
	$(I_{01})_b$		184	01111111	15	-15	0	01111111	24	E_{113}	V	$(I_{01})_b = I_{FS} \times \frac{127}{255} - 0.01(E_{113})$	—	—	—	—	mA		
	$\Delta(I_{01})$		185											$\Delta(I_{01}) = [(I_{01})_a - (I_{01})_b] \times 10^3$	0	16.0	0	16.0	µA
	$(I_{02})_a$		186	01000000	15	-15	0	01000000	24	E_{114}	V	$(I_{02})_a = I_{FS} \times \frac{64}{255} - 0.01(E_{114})$	—	—	—	—	mA		
	$(I_{02})_b$		187	00111111	15	-15	0	00111111	24	E_{115}	V	$(I_{02})_b = I_{FS} \times \frac{63}{255} - 0.01(E_{115})$	—	—	—	—	mA		
	$\Delta(I_{02})$		188											$\Delta(I_{02}) = [(I_{02})_a - (I_{02})_b] \times 10^3$	0	16.0	0	16.0	µA
	$(I_{03})_a$		189	00100000	15	-15	0	00100000	24	E_{116}	V	$(I_{03})_a = I_{FS} \times \frac{32}{255} - 0.01(E_{116})$	—	—	—	—	mA		
	$(I_{03})_b$		190	00011111	15	-15	0	00011111	24	E_{117}	V	$(I_{03})_b = I_{FS} \times \frac{31}{255} - 0.01(E_{117})$	—	—	—	—	mA		
	$\Delta(I_{03})$		191											$\Delta(I_{03}) = [(I_{03})_a - (I_{03})_b] \times 10^3$	0	16.0	0	16.0	µA
	$(I_{04})_a$		192	00010000	15	-15	0	00010000	24	E_{118}	V	$(I_{04})_a = I_{FS} \times \frac{16}{255} - 0.01(E_{118})$	—	—	—	—	mA		
	$(I_{04})_b$		193	00001111	15	-15	0	00001111	24	E_{119}	V	$(I_{04})_b = I_{FS} \times \frac{15}{255} - 0.01(E_{119})$	—	—	—	—	mA		
	$\Delta(I_{04})$		194											$\Delta(I_{04}) = [(I_{04})_a - (I_{04})_b] \times 10^3$	0	16.0	0	16.0	µA

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Equation				Limits				Units		
				1 - 8 logic state				9 10 11 12 13 14 15 logic state				16-23 logic state		Energized relays		Measured pin No. Value Unit		Device 01 Min Max		Device 02 Min Max		
				9 v	10 v	11 v	12 v	13 v	14 v	15 v	16-23 v	E ₁₂₀	V	E ₁₂₁	V	(I ₀₅) _a = I _{FS} × $\frac{8}{255}$ - 0.01(E ₁₂₀)	-	-	-	-		
$T_A = 125^\circ C$	(I ₀₅) _a	195	000001000	15	-15	15	-15	0	000001000	24	E ₁₂₀	V	(I ₀₅) _b = I _{FS} × $\frac{7}{255}$ - 0.01(E ₁₂₁)	-	-	-	-	mA				
	(I ₀₅) _b	196	000000111	15	-15	15	-15	0	000000111	24	E ₁₂₁	V	(I ₀₅) _b = I _{FS} × $\frac{7}{255}$ - 0.01(E ₁₂₁)	-	-	-	-	mA				
	ΔI_{05}	197											$\Delta I_{05} = [(I_{05})_a - (I_{05})_b] \times 10^3$	0	16.0	0	16.0	μA				
	(I ₀₆) _a	198	000000100	15	-15	15	-15	0	000000100	24	E ₁₂₂	V	(I ₀₆) _a = I _{FS} × $\frac{4}{255}$ - 0.01(E ₁₂₂)	-	-	-	-	mA				
ΔI_{06}	(I ₀₆) _b	199	000000011	15	-15	15	-15	0	000000011	24	E ₁₂₃	V	(I ₀₆) _b = I _{FS} × $\frac{3}{255}$ - 0.01(E ₁₂₃)	-	-	-	-	mA				
	ΔI_{06}	200											$\Delta I_{06} = [(I_{06})_a - (I_{06})_b] \times 10^3$	0	16.0	0	16.0	μA				
$(I_{07})_a$	(I ₀₇) _a	201	000000010	15	-15	15	-15	0	000000010	24	E ₁₂₄	V	(I ₀₇) _a = I _{FS} × $\frac{2}{255}$ - 0.01(E ₁₂₄)	-	-	-	-	mA				
	(I ₀₇) _b	202	000000001	15	-15	15	-15	0	000000001	24	E ₁₂₅	V	(I ₀₇) _b = I _{FS} × $\frac{1}{255}$ - 0.01(E ₁₂₅)	-	-	-	-	mA				
	ΔI_{07}	203											$\Delta I_{07} = [(I_{07})_a - (I_{07})_b] \times 10^3$	0	16.0	0	16.0	μA				
$(I_{08})_b$	(I ₀₈) _b	204	000000000	15	-15	15	-15	0	000000000	24	E ₁₂₆	V	(I ₀₈) _b = I _{FS} × $\frac{1}{255}$ - 0.01(E ₁₂₆)	-	-	-	-	mA				
	ΔI_{08}	205											$\Delta I_{08} = [(I_{07})_b - (I_{08})_b] \times 10^3$	0	16.0	0	16.0	μA				
	ΔI_{FS}	206											$I_{FS} - \overline{I_{FS}} \approx \Delta I_{FS}$	-8.0	8.0	-4.0	4.0	μA				
	I_{CC}^+	207	111111111	+15	-15	+15	-15	0		11	I ₃₉	mA	$I_{CC}^+ = I_{39}$	0.4	3.8	0.4	3.8	mA				
$T_A = -55^\circ C$	I_{CC}^-	3005	208	111111111						12	I ₄₀	mA	$I_{CC}^- = I_{40}$	-7.8	-7.8	-7.8	-7.8	mA				
	I_{FS}	209	J111111111						111111111	24	E ₁₂₇	V	$I_{FS} = 2 - 0.01(E_{127})$	1.94	2.04	1.984	2.000	mA				
	$\overline{I_{FS}}$	210	000000000						111111111	K2	24	E ₁₂₈	V	$\overline{I_{FS}} = 2 - 0.01(E_{128})$	1.94	2.04	1.984	2.000	mA			
	I_{ZS}	211	000000000							K4	24	E ₁₂₉	V	$I_{ZS} = -10(E_{129})$	-2.0	2.0	-1.0	1.0	μA			
$T_A = -55^\circ C$	$\overline{I_{ZS}}$	212	111111111							K2, K4	24	E ₁₃₀	V	$\overline{I_{ZS}} = -10(E_{130})$	-2.0	2.0	-1.0	1.0	μA			
	$P_{SS} I_{FS}^{+1}$	213	111111111	5.5	-18				111111111	24	E ₁₃₁	V	$P_{SS} I_{FS}^{+1} = -10(E_{131} - E_{132})$	-4.0	4.0	-4.0	4.0	μA				
	$P_{SS} I_{FS}^{+2}$	214	111111111	4.5	-18				111111111	24	E ₁₃₂	V										
	$P_{SS} I_{FS}^{+3}$	215	000000000	5.5	-18				111111111	K2	24	E ₁₃₃	V	$P_{SS} I_{FS}^{+3} = -10(E_{133} - E_{134})$	-4.0	4.0	-4.0	4.0	μA			
$P_{SS} I_{FS}^{+4}$	216	000000000	4.5	-18					111111111	K2	24	E ₁₃₄	V									
	$P_{SS} I_{FS}^{+5}$	217	111111111	18	-18				111111111	24	E ₁₃₅	V	$P_{SS} I_{FS}^{+5} = -10(E_{135} - E_{136})$	-8.0	8.0	-8.0	8.0	μA				
$P_{SS} I_{FS}^{+6}$	218	111111111	12	-18	◆	◆	◆	◆	111111111	24	E ₁₃₆	V										

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Adapter pin numbers												Equation			Limits			Device 01			Device 02									
			1 - 8 logic state			9 V			10 V			11 V			12 V			13 V			14 V			15 V			16-23 logic state						
			No.	Value	Unit	No.	Value	Unit	No.	Value	Unit	No.	Value	Unit	No.	Value	Unit	No.	Value	Unit	No.	Value	Unit	No.	Value	Unit	No.	Value	Unit				
$T_A = -55^{\circ}\text{C}$	$P_{SS}I_{FS}^{-2}$	219	00000000			18	-18	+15	-15	0		11111111	K2	24	E_{137}	V	$P_{SS}I_{FS}^{-2} = -10(E_{137}-E_{138})$	-8.0	8.0	-8.0	8.0	-8.0	8.0	-8.0	8.0	-8.0	8.0	μA					
	$P_{SS}I_{FS}^{-1}$	220	00000000			12	-18					11111111	K2	24	E_{138}	V																	μA
	$P_{SS}I_{FS}^{-1}$	221	11111111			18	-12					11111111	K2	24	E_{139}	V	$P_{SS}I_{FS}^{-1} = -10(E_{139}-E_{135})$	-8.0	8.0	-8.0	8.0	-8.0	8.0	-8.0	8.0	-8.0	8.0	μA					
	$P_{SS}I_{FS}^{-1}$	222	00000000			18	-12					11111111	K2	24	E_{140}	V	$P_{SS}I_{FS}^{-1} = -10(E_{140}-E_{137})$	-8.0	8.0	-8.0	8.0	-8.0	8.0	-8.0	8.0	-8.0	8.0	μA					
	$P_{SS}I_{FS}^{-2}$	223	11111111			18	5.5					11111111	K2	24	E_{141}	V	$P_{SS}I_{FS}^{-2} = -10(E_{141}-E_{142})$	-2.0	2.0	-2.0	2.0	-2.0	2.0	-2.0	2.0	-2.0	2.0	μA					
	$P_{SS}I_{FS}^{-2}$	224	11111111			18	4.5					11111111	K2	24	E_{142}	V	$P_{SS}I_{FS}^{-2} = -10(E_{143}-E_{144})$	-2.0	2.0	-2.0	2.0	-2.0	2.0	-2.0	2.0	-2.0	2.0	μA					
	$I_{FS}R_1$	225	00000000			18	4.5	♦	♦	♦	♦	11111111	K2	24	E_{143}	V																μA	
	$I_{FS}R_1$	226	00000000			18	4.5	♦	♦	♦	♦	11111111	K2	24	E_{144}	V																μA	
	$I_{FS}R_1$	227	11111111	15		15	-10	30	-5	0		K1,K4	26	E_{145}	V	$I_{FS}R_1 = 0.2E_{145}$	2.1		2.1		2.1		2.1									μA	
	$I_{FS}R_1$	228	00000000	15		15	-10	30	-5	0		K1,K2,K4	26	E_{146}	V	$I_{FS}R_1 = 0.2E_{146}$	2.1		2.1		2.1		2.1									μA	
	$I_{FS}R_2$	229	11111111	25		15	-12	30	-5	0		K1,K4	26	E_{147}	V	$I_{FS}R_2 = 0.2E_{147}$	4.2		4.2		4.2		4.2									μA	
	$I_{FS}R_2$	230	00000000	25		15	-12	30	-5	0		K1,K2,K4	26	E_{148}	V	$I_{FS}R_2 = 0.2E_{148}$	4.2		4.2		4.2		4.2									μA	
	I_{REF}	231	00000000	0		15	-15	15	-15	0		K3	10	I_{41}	A	$I_{REF} = I_{41} \times 10^6$	-3.0	0	-3.0	0	-3.0	0	-3.0	0									μA
	I_{IH1}	232	11000000										1	I_{42}	A	$I_{IH1} = I_{42} \times 10^6$	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	μA		
	I_{IH2}	233	01000000										2	I_{43}	A	$I_{IH2} = I_{43} \times 10^6$	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	μA		
	I_{IH3}	234	00100000										3	I_{44}	A	$I_{IH3} = I_{44} \times 10^6$	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	μA		
	I_{IH4}	235	00010000										4	I_{45}	A	$I_{IH4} = I_{45} \times 10^6$	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	μA		
	I_{IH5}	236	00001000										5	I_{46}	A	$I_{IH5} = I_{46} \times 10^6$	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	μA		
	I_{IH6}	237	00000100										6	I_{47}	A	$I_{IH6} = I_{47} \times 10^6$	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	μA		
	I_{IH7}	238	00000010										7	I_{48}	A	$I_{IH7} = I_{48} \times 10^6$	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	μA		
	I_{IH8}	239	00000001										8	I_{49}	A	$I_{IH8} = I_{49} \times 10^6$	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	-0.01	10.0	μA		
	I_{IL1}	240	10000000										1	I_{50}	A	$I_{IL1} = I_{50} \times 10^6$	-10.0		-10.0		-10.0		-10.0									μA	
	I_{IL2}	241	01000000										2	I_{51}	A	$I_{IL2} = I_{51} \times 10^6$	-10.0		-10.0		-10.0		-10.0									μA	
	I_{IL3}	242	00100000										3	I_{52}	A	$I_{IL3} = I_{52} \times 10^6$	-10.0		-10.0		-10.0		-10.0									μA	
	I_{IL4}	243	00010000										4	I_{53}	A	$I_{IL4} = I_{53} \times 10^6$	-10.0		-10.0		-10.0		-10.0									μA	

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL STD-883 method	Test no.	Adapter pin numbers								Equation	Limits				Units			
				1 - 8 logic state	9 .V	10 V	11 V	12 V	13 V	14 V	15 V		No. Measured pin Value	No. Unit	Device 01 Min	Device 01 Max	Device 02 Min	Device 02 Max		
$T_A = -55^\circ C$	I _{IL5}	244 ^{2/}	00000100	15	-15	15	-15	0				5	I ₅₄	A	I _{IL5} = I ₅₄ $\times 10^6$	-10.0	-10.0	A		
	I _{IL6}	245 ^{2/}	00000100									6	I ₅₅	A	I _{IL6} = I ₅₅ $\times 10^6$	-10.0	-10.0	A		
	I _{IL7}	246 ^{2/}	00000100									7	I ₅₆	A	I _{IL7} = I ₅₆ $\times 10^6$	-10.0	-10.0	A		
	I _{IL8}	247 ^{2/}	00000001									8	I ₅₇	A	I _{IL8} = I ₅₇ $\times 10^6$	-10.0	-10.0	A		
	V _{CAL1}	248										24	E ₁₄₉	V	V _{CAL1} = E ₁₄₉	—	—	V		
	I _{FS⁺}	249	11111111	15	-15	30	0	18	11111111			24	E ₁₅₀	V	I _{FS⁺} = 2 - 0.01(E ₁₅₀ - E ₁₄₉)	1.94	2.04	1.90	2.08	mA
$\overline{I_{FS^+}}$	I _{FS⁺}	250	00000000	15	-15	30	0	18	11111111	K2		24	E ₁₅₁	V	$\overline{I_{FS^+}} = 2 - 0.01(E_{151} - E_{149})$	1.94	2.04	1.90	2.08	mA
	V _{CAL2}	251	11111111	15	-15	15	-15	-10	11111111			24	E ₁₅₂	V	V _{CAL2} = E ₁₅₂	—	—	V		
	I _{FS⁻}	252	11111111	15	-15	15	-15	-10	11111111			24	E ₁₅₃	V	I _{FS⁻} = 2 - 0.01(E ₁₅₃ - E ₁₅₂)	1.94	2.04	1.90	2.08	mA
	$\overline{I_{FS^-}}$	253	00000000	15	-15	15	-15	-10	11111111	K2		24	E ₁₅₄	V	$\overline{I_{FS^-}} = 2 - 0.01(E_{154} - E_{152})$	1.94	2.04	1.90	2.08	mA
	ΔI_{FSC}	254													$\Delta I_{FSC} = 1000(I_{FS^+} - I_{FS^-})$	-4.0	4.0	-4.0	4.0	A
	$\overline{\Delta I_{FSC}}$	255													$\overline{\Delta I_{FSC}} = 1000(\overline{I_{FS^+}} - \overline{I_{FS^-}})$	-4.0	4.0	-4.0	4.0	A
V_{CAL3}	V _{CAL3}	256	00000000	15	-15	15	-15	0	00000000			24	E ₁₅₅	V	V _{CAL3} = E ₁₅₅	—	—	V		
	V _{CAL4}	257	11111111						11111111			24	E ₁₅₆	V	V _{CAL4} = E ₁₅₆	—	—	V		
	V _{CAL5}	258	11111111						11111111	K2		24	E ₁₅₇	V	V _{CAL5} = E ₁₅₇	—	—	V		
	V _{CAL6}	259	00000000						00000000	K2		24	E ₁₅₈	V	V _{CAL6} = E ₁₅₈	—	—	V		
	NL ₁	260	10000000	15	-15	15	-15	0	10000000			24	E ₁₅₉	V	NL ₁ = $\frac{(E_{159} - V_{CAL3})}{I_{FS} \times 10^3}$	—	—	%		
	NL ₂	261	01000000	15	-15	15	-15	0	01000000			24	E ₁₆₀	V	$NL_2 = \frac{(E_{160} - V_{CAL3})}{I_{FS} \times 10^3} - \frac{(64)}{(255)} \frac{(V_{CAL4} - V_{CAL3})}{I_{FS} \times 10^3}$	—	—	%		

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MTI-STD-883 method	Test no.	Adapter pin numbers								Energized relays	Measured pin No.	Limits		Device 01 Min	Device 01 Max	Device 02 Min	Device 02 Max	Units	
				1 - 8 logic state	9 v	10 v	11 v	12 v	13 v	14 v	15 v			Value	Unit						
$T_A = -55^{\circ}\text{C}$	NL ₃		262	00100000			15	-15	15	-15	0	00100000	24	E_{161}	v	$NL_3 = \frac{(E_{161}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(32)}{(255)} \frac{(V_{CAL4}-V_{CAL3})}{I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₄		263	00010000								00010000	24	E_{162}	v	$NL_4 = \frac{(E_{162}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(16)}{(255)} \frac{(V_{CAL4}-V_{CAL3})}{I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₅		264	00001000								00001000	24	E_{163}	v	$NL_5 = \frac{(E_{163}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(8)}{(255)} \frac{(V_{CAL4}-V_{CAL3})}{I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₆		265	00000100								00000100	24	E_{164}	v	$NL_6 = \frac{(E_{164}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(4)}{(255)} \frac{(V_{CAL4}-V_{CAL3})}{I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₇		266	00000010								00000010	24	E_{165}	v	$NL_7 = \frac{(E_{165}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(2)}{(255)} \frac{(V_{CAL4}-V_{CAL3})}{I_{FS} \times 10^3}$	—	—	—	—	%
	NL ₈		267	00000001								00000001	24	E_{166}	v	$NL_8 = \frac{(E_{166}-V_{CAL3})}{I_{FS} \times 10^3} - \frac{(1)}{(255)} \frac{(V_{CAL4}-V_{CAL3})}{I_{FS} \times 10^3}$	—	—	—	—	%
	$\overline{NL_1}$		268	01111111								10000000	24	E_{167}	v	$\overline{NL_1} = \frac{(E_{167}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(128)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	—	—	—	—	%

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Measured pin No.	Unit	Equation	Limits		Device 01 Min	Device 02 Min	Device 01 Max	Device 02 Max	Units
				1 - 8 logic state	9 v	10 v	11 v	12 v	13 v	14 v	15 v				Device 01 Max	Device 02 Max					
$T_A = -55^{\circ}\text{C}$	$\overline{NL_2}$		269	1011111	15	-15	15	-15	0	01000000		24	E_{168}	v	$\overline{NL_2} = \frac{(E_{168}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(64)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	$\overline{NL_3}$		270	1101111						00100000		24	E_{169}	v	$\overline{NL_3} = \frac{(E_{169}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(32)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	$\overline{NL_4}$		271	1110111						00010000		24	E_{170}	v	$\overline{NL_4} = \frac{(E_{170}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(16)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	$\overline{NL_5}$		272	1111011						00001000		24	E_{171}	v	$\overline{NL_5} = \frac{(E_{171}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(8)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	$\overline{NL_6}$		273	1111101						00000100		24	E_{172}	v	$\overline{NL_6} = \frac{(E_{172}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(4)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	$\overline{NL_7}$		274	11111101						00000010		24	E_{173}	v	$\overline{NL_7} = \frac{(E_{173}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(2)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%
	$\overline{NL_8}$		275	11111110						00000001		24	E_{174}	v	$\overline{NL_8} = \frac{(E_{174}-V_{CAL5})}{I_{FS} \times 10^3} - \frac{(1)}{(255)} \frac{(V_{CAL6}-V_{CAL5})}{I_{FS} \times 10^3}$	-	-	-	-	-	%

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Adapter pin numbers								Measured bin No.	Measured bin Unit	Equation		Limits			
			1 - 8 logic state	9 V	10 V	11 V	12 V	13 V	14 V	15 V			Device 01 Min	Device 01 Max	Device 02 Min	Device 02 Max	Units	
3	ΣNL^+	276											$2NL^+ = NL_1 + NL_k + \dots$ (i,k = bits having positive errors)	0	0.19	0	0.10	%
$T_A = -55^\circ C$	ΣNL^+	277											$2NL^+ = NL_{j1} + NL_{k1} + \dots$	0	0.19	0	0.10	%
	ΣNL^-	278											$2NL^- = NL_m + NL_h + \dots$ (m,h = bits having negative errors)	-0.19	0	-0.10	0	%
	ΣNL^-	279											$2NL^- = NL_{m1} + NL_{h1} + \dots$	-0.19	0	-0.10	0	%
	ΔNL	280											$\Delta NL = 2NL^+ - 2NL^- $	-0.05	0.05	-0.03	0.03	%
	ΔNL	281											$\Delta NL = 2NL^+ - 2NL^- $	-0.05	0.05	-0.03	0.03	%
	NL^+	282											$NL^+ = 2NL^+ + \Delta NL $	0	0.19	0	0.10	%
	NL^+	283											$NL^+ = 2NL^+ + \Delta NL $	0	0.19	0	0.10	%
	NL^-	284											$NL^- = 2NL^- + \Delta NL $	0	0.19	0	0.10	%
	NL^-	285											$NL^- = 2NL^- + \Delta NL $	0	0.19	0	0.10	%
$(I_{01})_a$		286	10000000	15	-15	15	-15	0	10000000	24	E_{175}	V	$(I_{01})_a = I_{FS} \times \frac{128}{255} - 0.01(E_{175})$	-	-	-	-	mA
$(I_{01})_b$		287	01111111	15	-15	15	-15	0	01111111	24	E_{176}	V	$(I_{01})_b = I_{FS} \times \frac{127}{255} - 0.01(E_{176})$	-	-	-	-	mA
$\Delta(I_{01})$		288											$\Delta(I_{01}) = [(I_{01})_a - (I_{01})_b] \times 10^3$	0	16.0	0	16.0	μA
$(I_{02})_a$		289	01000000	15	-15	15	-15	0	01000000	24	E_{177}	V	$(I_{02})_a = I_{FS} \times \frac{64}{255} - 0.01(E_{177})$	-	-	-	-	mA
$(I_{02})_b$		290	00111111	15	-15	15	-15	0	00111111	24	E_{178}	V	$(I_{02})_b = I_{FS} \times \frac{63}{255} - 0.01(E_{178})$	-	-	-	-	mA
$\Delta(I_{02})$		291											$\Delta(I_{02}) = [(I_{02})_a - (I_{02})_b] \times 10^3$	0	16.0	0	16.0	μA
$(I_{03})_a$		292	00100000	15	-15	15	-15	0	00100000	24	E_{179}	V	$(I_{03})_a = I_{FS} \times \frac{32}{255} - 0.01(E_{179})$	-	-	-	-	mA
$(I_{03})_b$		293	00011111	15	-15	15	-15	0	00011111	24	E_{180}	V	$(I_{03})_b = I_{FS} \times \frac{31}{255} - 0.01(E_{180})$	-	-	-	-	mA
$\Delta(I_{03})$		294											$\Delta(I_{03}) = [(I_{03})_a - (I_{03})_b] \times 10^3$	0	16.0	0	16.0	μA
$(I_{04})_a$		295	00010000	15	-15	15	-15	0	00010000	24	E_{181}	V	$(I_{04})_a = I_{FS} \times \frac{16}{255} - 0.01(E_{181})$	-	-	-	-	mA
$(I_{04})_b$		296	00001111	15	-15	15	-15	0	00001111	24	E_{182}	V	$(I_{04})_b = I_{FS} \times \frac{15}{255} - 0.01(E_{182})$	-	-	-	-	mA
$\Delta(I_{04})$		297											$\Delta(I_{04}) = [(I_{04})_a - (I_{04})_b] \times 10^3$	0	16.0	0	16.0	μA

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Equation		Limits		Units			
				1 - 8 logic state	9 v	10 v	11 v	12 v	13 v	14 v	15 v	16-23 logic state	Energized relays	No. Measured pin	Device 01 Min	Device 01 Max	Device 02 Min	Device 02 Max	
$T_A = -55^\circ C$	$(I_{05})_a$	286	00001000		15	-15	15	-15	0	00001000		24	E_{183} v	$(I_{05})_a = I_{FS} \times \frac{8}{255} - 0.01(E_{183})$	—	—	—	—	mA
	$(I_{05})_b$	299	00000111		15	-15	15	-15	0	00000111		24	E_{184} v	$(I_{05})_b = I_{FS} \times \frac{7}{255} - 0.01(E_{184})$	—	—	—	—	mA
	$\Delta(I_{05})$	300												$\Delta(I_{05}) = [(I_{05})_a - (I_{05})_b] \times 10^3$	0	16.0	0	16.0	µA
	$(I_{06})_a$	301	00000100		15	-15	15	-15	0	00000100		24	E_{185} v	$(I_{06})_a = I_{FS} \times \frac{4}{255} - 0.01(E_{185})$	—	—	—	—	mA
$T_A = 25^\circ C$	$(I_{06})_b$	302	00000011		15	-15	15	-15	0	00000011		24	E_{186} v	$(I_{06})_b = I_{FS} \times \frac{3}{255} - 0.01(E_{186})$	—	—	—	—	mA
	$\Delta(I_{06})$	303												$\Delta(I_{06}) = [(I_{06})_a - (I_{06})_b] \times 10^3$	0	16.0	0	16.0	µA
	$(I_{07})_a$	304	00000010		15	-15	15	-15	0	00000010		24	E_{187} v	$(I_{07})_a = I_{FS} \times \frac{2}{255} - 0.01(E_{187})$	—	—	—	—	mA
$T_A = 125^\circ C$	$(I_{07})_b$	305	00000001		15	-15	15	-15	0	00000001		24	E_{188} v	$(I_{07})_b = I_{FS} \times \frac{1}{255} - 0.01(E_{188})$	—	—	—	—	mA
	$\Delta(I_{07})$	306												$\Delta(I_{07}) = [(I_{07})_a - (I_{07})_b] \times 10^3$	0	16.0	0	16.0	µA
	$(I_{08})_b$	307	00000000		15	-15	15	-15	0	00000000		24	E_{189} v	$(I_{08})_b = I_{FS} \times \frac{1}{255} - 0.01(E_{189})$	—	—	—	—	mA
$T_A = 125^\circ C$	$\Delta(I_{08})$	308												$\Delta(I_{08}) = [(I_{07})_b - (I_{08})_b] \times 10^3$	0	16.0	0	16.0	µA
	ΔI_{FS}	309												$I_{FS} - \overline{I_{FS}} = \Delta I_{FS}$	-8.0	8.0	-4.0	4.0	µA
	$TC(I_{FS})$	310												$TC(I_{FS}) = \frac{(E_1 - E_{50})}{E_1} \times 10^4$	-50	50	-50	50	PPM/°C
$T_A = 125^\circ C$	$TC(I_{FS})$	311												$TC(I_{FS}) = \frac{(E_1 - E_{126})}{0.8E_1} \times 10^4$	-50	50	-50	50	PPM/°C
	$TC(\overline{I_{FS}})$	312												$TC(\overline{I_{FS}}) = \frac{(E_2 - E_{50})}{E_2} \times 10^4$	-50	50	-50	50	PPM/°C
	$TC(\overline{I_{FS}})$	313												$TC(\overline{I_{FS}}) = \frac{(E_2 - E_{127})}{0.8E_2} \times 10^4$	-50	50	-50	50	PPM/°C
$T_A = 125^\circ C$	t_{PHL}	314												See figure 7. $V_L = 2.7$ v, V_{out} high-to-low transition, S1-OFF (V_{IN} low-to-high)	6	60	6	60	ns
	t_{PLH}	315												See figure 7. $V_L = 0.7$ v, V_{out} low-to-high transition, S1-OFF (V_{IN} high-to-low)	6	60	6	60	ns
$T_A = 125^\circ C$	t_{PHL}	316												See figure 7. $V_L = 2.7$ v, V_{out} high-to-low transition, S1-OFF (V_{IN} low-to-high)	6	60	6	60	ns

See footnotes at end of table.

TABLE III. Group A inspection for device types 01 and 02 - Continued.

Subgroup	Symbol	MIL-STD-883 method	Test no.	Adapter pin numbers								Energized relays	Measured pin No.	Equation	Limits				
				-8	9	10	11	12	13	14	15				Min	Max	Min	Max	
10 $T_A = 125^\circ C$	t_{PLH}		317	See figure 7. $V_L = 0.7 V$, V_{OUT} low-to-high transition, S1 OFF (V_N high-to-low)											6	60	6	60	
$T_A = -55^\circ C$	t_{PDLH}		318	See figure 7. $V_L = 2.7 V$, V_{OUT} high-to-low transition, S1-OFF (V_N low-to-high)											6	60	6	60	
	t_{PLH}		319	See figure 7. $V_L = 0.7 V$, V_{OUT} low-to-high transition, S1-OFF (V_N high-to-low)											6	60	6	60	
	$\frac{dI_0}{dt}$		320	See figure 8. $V_L = 5 Vdc$												6	60	6	60
	t_{SHL}		321	See figure 7. $V_L = 2.7 V$, V_{OUT} high-to-low transition, S1-OFF (V_N low-to-high)											10	135	10	135	
	t_{SBL}		322	See figure 7. $V_L = 0.7 V$, V_{OUT} low-to-high transition, S1-OFF (V_N high-to-low)											10	135	10	135	

NOTES:

1/ The measurement of I_{FS} and T_{FS} can be made directly as a voltage measurement at pin 26 ($I_{FS} = [E_{pin26}/5000]mA$) provided that measurement accuracy is $\pm 0.1\%$ or better. If the measurement is made in accordance with table III, the reference D/A converter must be calibrated for a full scale current of $2.0 \text{ mA} \pm 0.1\%$.

2/ For tests 26-33, 129-136 and 232-239, the logic input voltage shall be +18 V. For tests 34-41, 137-144 and 240-247, the logic input voltage shall be -10.0 V.

TABLE IV. Group C end point electrical parameters.
 $(T_A = 25^\circ\text{C}; \pm V_{CC} = \pm 15 \text{ V})$

Test no.	Symbol	Device type 01				Device type 02			
		Limits		Delta	Units	Limits		Delta	Units
		Min	Max			Min	Max		
3	I_{FS}	1.94	2.04	0.01	mA	1.984	2.000	0.005	mA
4	\bar{I}_{FS}	1.94	2.04	0.01	mA	1.984	2.000	0.005	mA
5	I_{ZS}	-2.0	+2.0	0.5	μA	-1.0	+1.0	0.3	μA
6	\bar{I}_{ZS}	-2.0	+2.0	0.5	μA	-1.0	+1.0	0.3	μA

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Notes. The notes specified in MIL-M-38510 are applicable to this specification.

6.2 Intended use. Microcircuits conforming to this specification are intended for use for Government microcircuit applications (original equipment) and logistic purposes.

6.3 Ordering data. The contract or order should specify the following:

- a. Complete part number (see 1.2).
- b. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
- c. Requirement for certificate of compliance, if applicable.
- d. Requirements for notification of change of product or process to procuring activity in addition to notification to the qualifying activity, if applicable.
- e. Requirements for packaging and packing.
- f. Requirements for failure analysis (including required test condition of method 5003, MIL-STD-883, corrective action and reporting of results, if applicable).
- g. Requirements for product assurance options.
- h. Requirements for carriers, special lead lengths or lead forming, if applicable. These requirements shall not affect the part number. Unless otherwise specified, these requirements will not apply to direct purchase by or direct shipment to the Government.

6.4 Abbreviations, symbols, and definitions. Abbreviations, symbols, and definitions used herein are defined in MIL-M-38510 and MIL-STD-1331.

6.5 Logistic support. Lead materials and finishes (see 3.3) are interchangeable. Unless otherwise specified, microcircuits procured for Government logistic support will be procured to device class B (see 1.2.2), lead material and finish C (see 3.3). Longer length leads and lead forming shall not affect the part number.

6.6 Substitutability. The cross-reference information below is presented for the convenience of users. Microcircuits covered by this specification will functionally replace the listed Generic-Industry type. Generic-Industry microcircuit types may not have equivalent operational performance characteristics across military temperature ranges or reliability factors equivalent to MIL-M-38510 device types and may have slight physical variations in relation to case size. The presence of this information shall not be deemed as permitting substitution of Generic-Industry types for MIL-M-38510 types or as a waiver of any of the provisions of MIL-M-38510.

<u>Military device type</u>	<u>Generic-Industry type</u>
01	DAC-08
02	DAC-08A

Custodians:

Army - ER
Navy - EC
Air Force - 17

Review activities:

Army - AR, MI, HD
Navy - SD
Air Force - 99
DLA - ES
NASA - NA

User activities:

Army - SM
Navy - CG, MC, AS, OS
Air Force - 19

Preparing activity:
Air Force - 17

Agent:
DLA - ES

(Project 5962-0273)

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DIGITAL-TO-ANALOG CONVERTERS, MONOLITHIC SILICON**

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